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**Compal Confidential**

**C5V01 MB Schematic Document**

**LA-E892P**

**Rev: 1.A**

**2017.04.18**

Security Classification	Compal Secret Data			Compal Electronics, Inc.		
Issued Date	2016/11/04	Deciphered Date	2018/11/04	Title	Cover Sheet	
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HDMI Conn.



page 29

DDI1  
HDMI x 4 lanes

eDP



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eDP

DDI

eMMC

page 34

eMMC



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PCIe 3.0 x4  
8GT/s  
Port 9-12Flexible IO  
Base-U PCIe2.0  
Premium-U PCIe3.0Nvidia N16S-GTR /  
N17S-G1  
with GDDR5 x2  
page 21~27PCIe 3.0 x 4  
8GT/s  
port 1-4PCIe 1.0  
2.5GT/s  
port 6  
page 31PCIe 1.0  
2.5GT/s  
port 5SATA3.0  
6.0 Gb/s  
port 7  
(SATA0)SATA3.0  
6.0 Gb/s  
port 8  
(SATA1)LAN(GbE)  
Realtek 8411B  
page 30SATA HDD  
Conn.

page 33

SATA CDROM  
Conn.

page 33

SD conn.

RJ45 conn.



RTC CKT.

page 15

Fan Control

page 39

Power On/Off CKT.

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DC/DC Interface CKT.

page 40

Power Circuit DC/DC

page 41~54

Sub Board

LS-E891  
IO/B

page 36

LS-E892  
Hall Sensor/B

page 38

Intel Kabylake U

Kabylake U  
Kabylake PCH-LP(MCP)  
(KBL-U\_2+2)  
(KBL-RU\_4+2)

Processor

Dual Core + GT2  
Quad Core + GT2

15W

1356pin BGA  
page 07~18

LPC/eSPI BUS

CLK=24MHz

ENE  
KB9022

page 37

Int.KBD



page 38

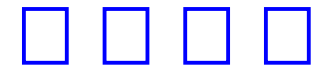
Touch Pad

PS2 (from EC) / I2C (from SOC)  
USB2 port 8 (FP)

page 38

Interleaved Memory

DDR4-ON BOARD 4G 8Gbx16



page 19

260pin DDR4-SO-DIMM X1



page 20

Memory BUS  
Dual Channel

1.2V DDR4 1866/2133

USB 3.0  
conn x1  
USB3 port 1  
USB2 port 1

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USB 2.0  
conn x2  
USB2 port3,4  
on Sub/B

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CMOS  
Camera  
USB2 port 7

page 28

USB TypeC  
conn x1  
USB3 port 2,3  
USB2 port2

page 35

USBx8 48MHz

HD Audio

3.3V 24MHz

HDA Codec  
ALC255

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Touch  
ScreenUSB2 port 6  
page 28

SPI

SPI ROM  
64Mb

page 9

Int. Speaker

page 32

Int. DMIC  
on Camera

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UAI  
on Sub/B

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Board ID Table for AD channel

Vcc	3.3V +/- 5%					
Ra	100K +/- 1%					
Board ID	Rb	V <sub>BI</sub> D min	V <sub>BI</sub> D typ	V <sub>BI</sub> D max	EC AD3	PCB Revision
0	0	0 V	0 V	0.300 V	0x00 - 0x13	0.1(EVT)
1	12K +/- 1%	0.347 V	0.345 V	0.360 V	0x14 - 0x1E	1.0(DVT)
2	15K +/- 1%	0.423 V	0.430 V	0.438 V	0x1F - 0x25	1.A(PVT)
3	20K +/- 1%	0.541 V	0.550 V	0.559 V	0x26 - 0x30	1.A(MP)
4	27K +/- 1%	0.691 V	0.702 V	0.713 V	0x31 - 0x3A	1.A(EA17PVT)
5	33K +/- 1%	0.807 V	0.819 V	0.831 V	0x3B - 0x45	1.A(EA17MP)
6	43K +/- 1%	0.978 V	0.992 V	1.006 V	0x46 - 0x54	
7	56K +/- 1%	1.169 V	1.185 V	1.200 V	0x55 - 0x64	

BOM Structure Table

BOM Option Table	
Item	BOM Structure
Unpop	@
Connector	CONN@
Acer BYOC	BYOC@ / NBYOC@
CODEC(ALC255)	255@
EC Mode Select	LPC@ / ESPI@
For Intel CMC	CMC@
LAN Mode Select	SWR@ / LDO@
EMI requirement	EMI@ / @EMI@
ESD requirement	ESD@ / @ESD@
RF requirement	@RF@
CPU Selection	U42@/U22@
SkyLake or KabyLake	SKL@ / KBL@
TPM	TPM@
Finger Print	FP@/FPEMC@
UMA or DGPU	UMA@/VGA@
DGPU Serial Select	N16X@/N17S@

BOM Option Table	
Item	BOM Structure
MB Stage	EVT@/DVT@/PVT@/MP@
ODD Support	ODD@
G Sensor	BA@
For over 3 cell battery	3S@
C5V01, D5PR1	EA15@
D7W01	EA17@
D7W01 MB Stage	EA17PVT@/EA17MP@
N16SGTR or N17SG1	N16SGTR@ / N17SG1@
BOM Select	X76@
VRAM BOM Select	X7604@ ~ X7609@
Memory Select	X7601@ ~ X7603@
Memory Mode	SDP@ / DDP@
CPU Code	SR2UW@ QLDP@/QLDM@/QLDN@ QLYK@/QLYJ@/QLYH@  SR2ZW@/SR2ZU@/SR2ZV@ SR343@/SR342@/SR341@  QN5D@/QN5C@

Power State

STATE	SIGNAL						
	SLP_S3#	SLP_S4#	SLP_S5#	+VALW	+V	+VS	Clock
S0 (Full ON)	HIGH	HIGH	HIGH	ON	ON	ON	ON
S3 (Suspend to RAM)	LOW	HIGH	HIGH	ON	ON	OFF	OFF
S4 (Suspend to Disk)	LOW	LOW	HIGH	ON	OFF	OFF	OFF
S5 (Soft OFF)	LOW	LOW	LOW	ON	OFF	OFF	OFF

Voltage Rails

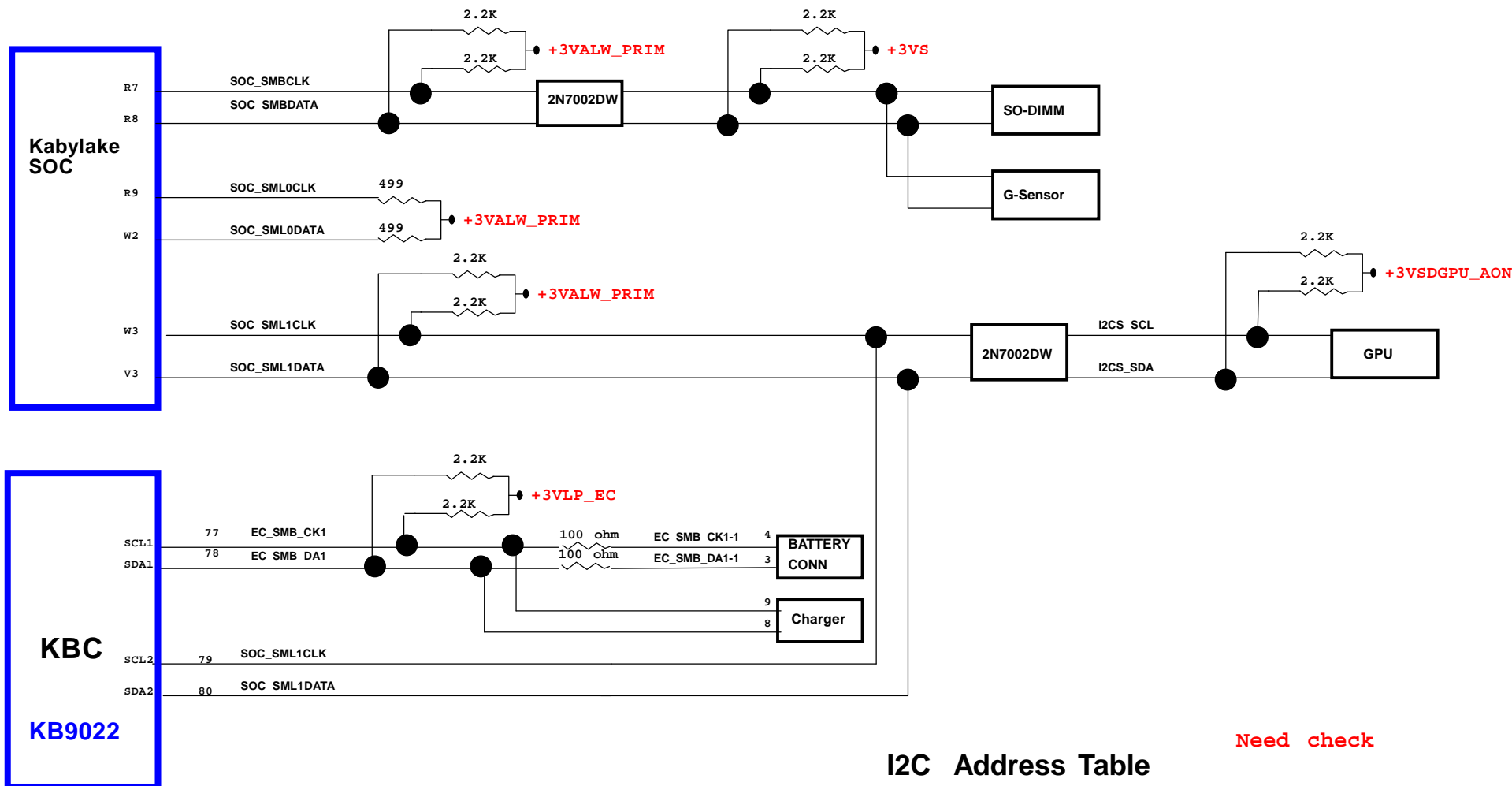
Power Plane	Description	S0	S3	S4/S5
+19V_VIN	Adapter power supply	N/A	N/A	N/A
+17.4V_BATT	Battery power supply	N/A	N/A	N/A
+19VB	AC or battery power rail for power circuit.	N/A	N/A	N/A
+VCC_CORE	Processor IA Cores Power Rail	ON	OFF	OFF
+VCC_GT	Processor Graphics Power Rails	ON	OFF	OFF
+VCC_SA	System Agent power rail	ON	OFF	OFF
+0.6VS_VTT	DDR +0.6VS power rail for DDR terminator .	ON	OFF	OFF
+1.0VALW_PRIM	+1.0V Always power rail	ON	ON	ON*1
+1.0V_VCCSTU	Sustain voltage for processor in Standby modes	ON	ON	OFF
+VCCIO	CPU IO power rail	ON	OFF	OFF
+1.0VS_VCCSTG	+1.0VALW_PRIM Gated version of VCCST	ON	OFF	OFF
+1.2V_VDDQ	DDR4 +1.2V Power Rail	ON	ON	OFF
+1.8VALW_PRIM	+1.8V Always power rail	ON	ON	ON*1
+1.8VS	System +1.8V power rail	ON	OFF	OFF
+3VLP	+19VB to +3VLP power rail for suspend power	ON	ON	ON
+3VALW	System +3VALW always on power rail	ON	ON	ON*1
+3VS	System +3V power rail	ON	OFF	OFF
+5VALW	+5V Always power rail	ON	ON	ON
+5VS	System +5V power rail	ON	OFF	OFF
+RTCVCC	RTC Battery Power	ON	ON	ON
+1.05VS_1.0VSDGPU	+1.05VS power rail for N16X/ +1.0VS power rail for N17S	ON*2	OFF	OFF
+1.35VSDGPU	+1.35VS power rail for GPU	ON*2	OFF	OFF
+3VS_1.8VSDGPU_AON	+3VS power rail for N16X/ +1.8VS power rail for N17S(AON)	ON*2	OFF	OFF
+3VS_1.8VSDGPU_MAIN	+3VS power rail for N16X/ +1.8VS power rail for N17S(MAIN)	ON*2	OFF	OFF
+VGA_CORE	Core power for discrete GPU	ON*2	OFF	OFF
Note : ON*1 means power plane is ON only when WOL enable and RTC wake at BIOS setting, otherwise it is OFF. ON*2 power plane is ON when DGPU turn on				

43 level BOM table

43 Level	Description	BOM Structure
431A7EBOL07	SMT MB AE892 C5V01 N172G I36006 HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N17S@/N17SG1@/NBYOC@/SR2UW@/U22@/VGA@/X7601@/X7607@/X4E02@/EA15@
431A7EBOL08	SMT MB AE892 C5V01 N172G I57200 1.4HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N17S@/N17SG1@/NBYOC@/SR22U@/U22@/VGA@/X7601@/X7607@/X4E02@/EA15@
431A7EBOL10	SMT MB AE892 C5V01 N172G I77500 1.4HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N17S@/N17SG1@/NBYOC@/SR22V@/U22@/VGA@/X7601@/X7607@/X4E02@/EA15@
431A7EBOL11	SMT MB AE892 C5V01 SGT2G I3~6006U HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N16SGTR@/N16X@/NBYOC@/SR2UW@/U22@/VGA@/X7601@/X7604@/X4E01@/EA15@
431A7EBOL15	SMT MB AE892 C5V01 SGT2G I77500 1.4HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N16SGTR@/N16X@/NBYOC@/SR22V@/U22@/VGA@/X7601@/X7604@/X4E01@/EA15@
431A7EBOL16	SMT MB AE892 C5V01 SGT2G I3~7100U HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N16SGTR@/N16X@/NBYOC@/SR343@/U22@/VGA@/X7601@/X7604@/X4E01@/EA15@
431A7EBOL17	SMT MB AE892 C5V01 SGT2G I5~7200U HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N16SGTR@/N16X@/NBYOC@/SR342@/U22@/VGA@/X7601@/X7604@/X4E01@/EA15@
431A7EBOL18	SMT MB AE892 C5V01 SGT2G I7~7500U HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N16SGTR@/N16X@/NBYOC@/SR341@/U22@/VGA@/X7601@/X7604@/X4E01@/EA15@
431A7EBOL19	SMT MB AE892 C5V01 N172G I3~7100U HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N17S@/N17SG1@/NBYOC@/SR343@/U22@/VGA@/X7601@/X7607@/X4E02@/EA15@
431A7EBOL20	SMT MB AE892 C5V01 N172G I5~7200U HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N17S@/N17SG1@/NBYOC@/SR342@/U22@/VGA@/X7601@/X7607@/X4E02@/EA15@
431A7EBOL21	SMT MB AE892 C5V01 N172G I7~7500U HDMI	255@/3S@/CHG@/CMC@/MP@/KBL@/LDO@/LPC@/N17S@/N17SG1@/NBYOC@/SR341@/U22@/VGA@/X7601@/X7607@/X4E02@/EA15@

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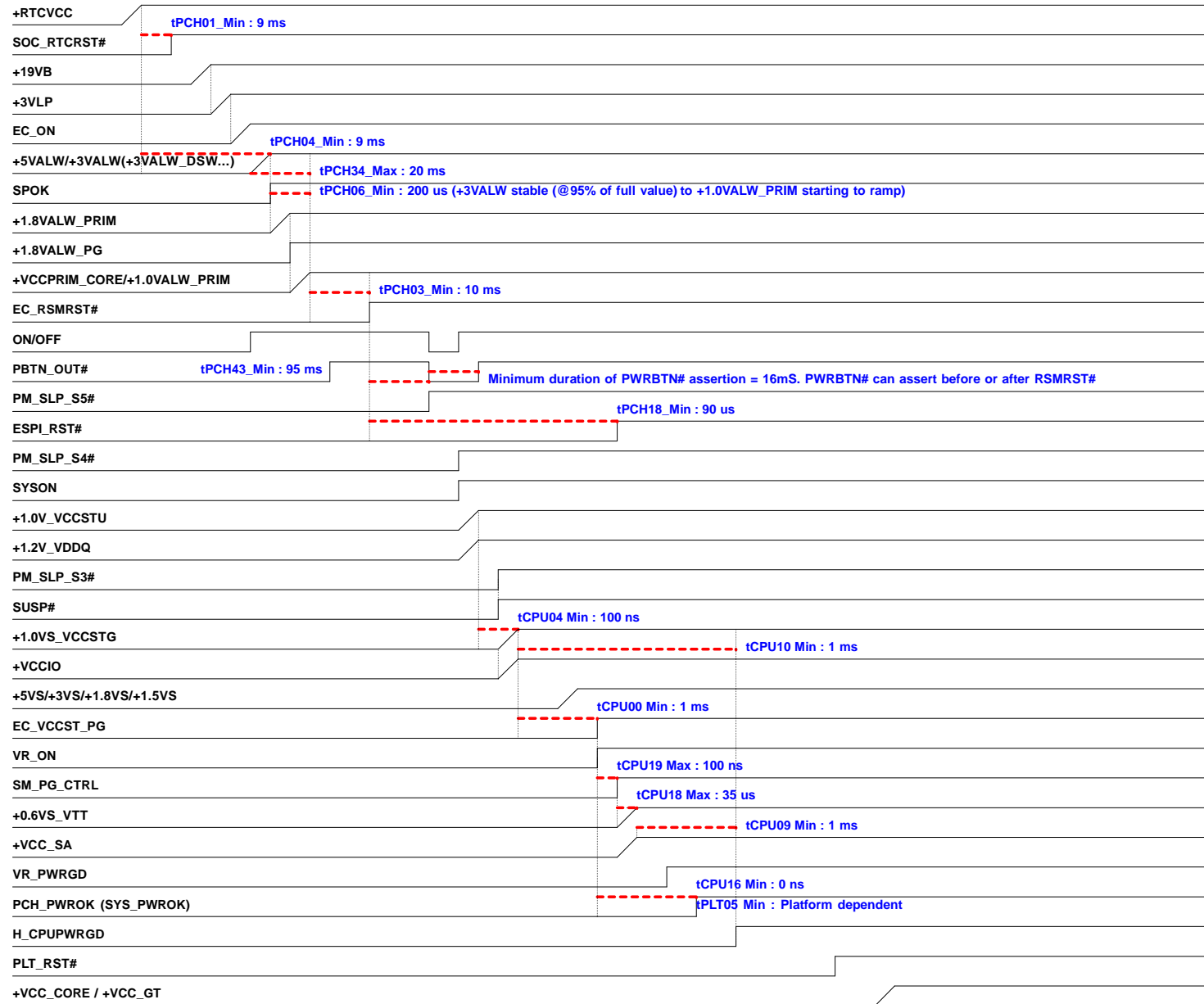
Need check

## I2C Address Table

BUS	Device	Address(7 bit)	Address(8bit)	
			Write	Read
I2C_0 (+3VS)	Reserved			
I2C_1 (+3VALW_PGPPC)	TM-P2969-001 (TP)	0x2C		
	SB8787-1200 (TP-ELAN)	0x15		
SOC_SMBCLK +3VS	SO-DIMM	0xA4		
	G-Sensor	0x30		
SOC_SML1CLK +3VALW_PRIM	VGA	0x9E		
	EC			
EC_SMB_CK1 +3VLP	BQ24735 (Charger IC)	0x12		
	BATTERY PACK	0x16		

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				Size Custom	Document Number
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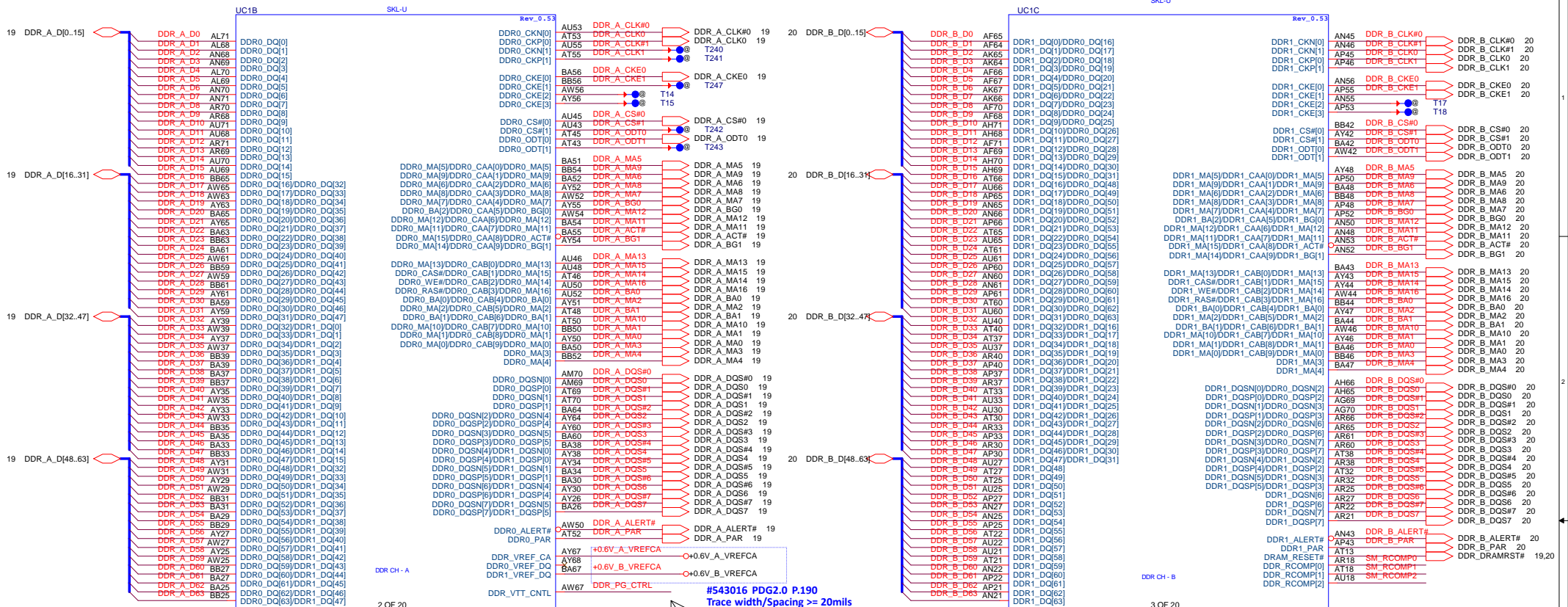
# PWR Sequence\_SKL-U2+2\_DDR3L\_Value\_NON CS



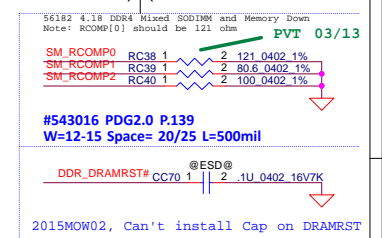
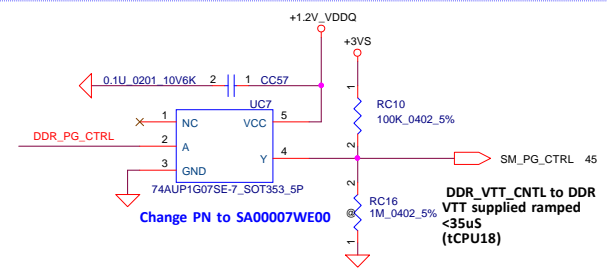
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# Interleaved Memory



#543016 PDG2.0 P.190  
Trace width/Spacing >= 20mils  
Place component near SODIMM



**PCB Number**

ZZZ PVT 03/13

**Skylake CPU Part Number**

UC1 CPU\_SKL\_D1\_i3-6006U\_2.0G SR2UW@ SA0000ACL30

**Kabylake U42 CPU Part Number**

UC1 CPU\_KBL\_Y0\_U42\_I5\_1.4G QNSD@ SA0000AR010

UC1 CPU\_KBL\_Y0\_U42\_I7\_1.8G QNSC@ SA0000AQZ10

**Kabylake CPU Part Number**

UC1 HDCP1.4 CPU\_KBL\_H0\_i3-7100U\_2.4G QNDP@ SA0000A3820

UC1 HDCP1.4 CPU\_KBL\_H0\_i5-7200U\_2.5G QNDM@ SA0000A3720

UC1 HDCP1.4 CPU\_KBL\_H0\_i7-7500U\_2.7G QNDN@ SA0000A3400

UC1 HDCP1.4 CPU\_KBL\_H0\_i3-7100U\_2.4G SR2ZU@ SA0000A3860

UC1 HDCP1.4 CPU\_KBL\_H0\_i5-7200U\_2.5G SR2ZV@ SA0000A3760

UC1 HDCP1.4 CPU\_KBL\_H0\_i7-7500U\_2.7G SR2ZV@ SA0000A3450

**Kabylake CPU Part Number**

UC1 HDCP2.2 CPU\_KBL\_H0\_i3-7100U\_2.4G QNDP@ SA0000A38K0

UC1 HDCP2.2 CPU\_KBL\_H0\_i5-7200U\_2.5G QNDM@ SA0000A37L0

UC1 HDCP2.2 CPU\_KBL\_H0\_i7-7500U\_2.7G QNDN@ SA0000A34J0

UC1 HDCP2.2 CPU\_KBL\_H0\_i3-7100U\_2.4G SR2ZU@ SA0000A38M0

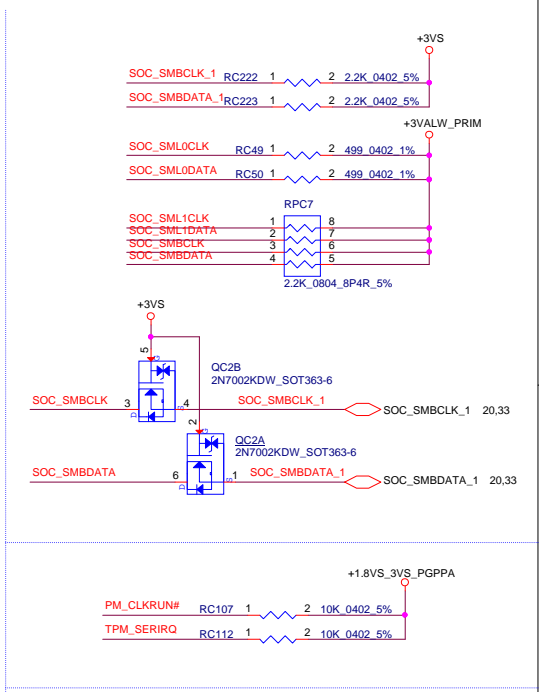
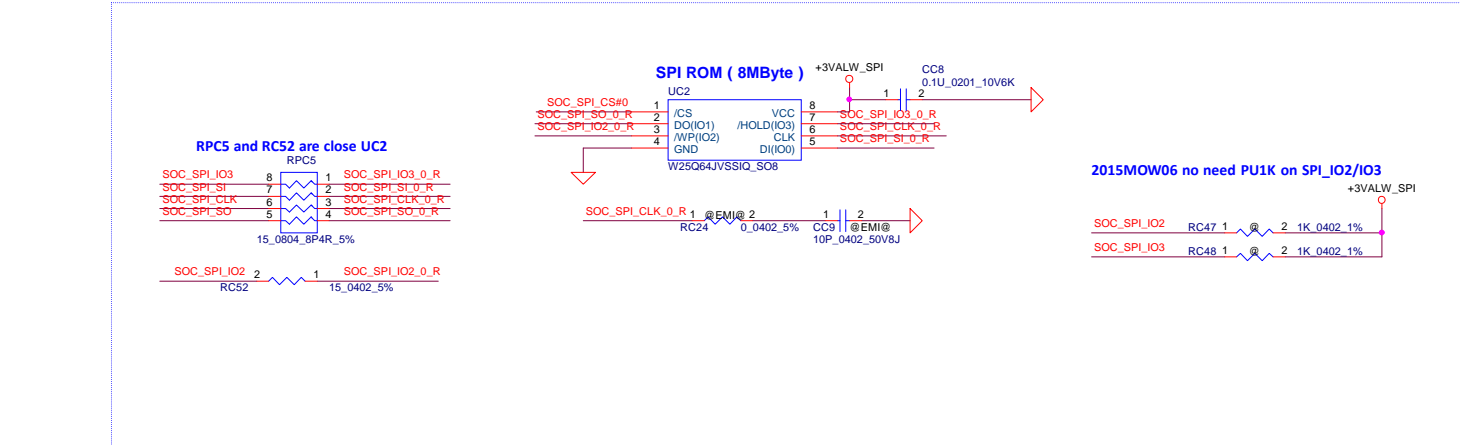
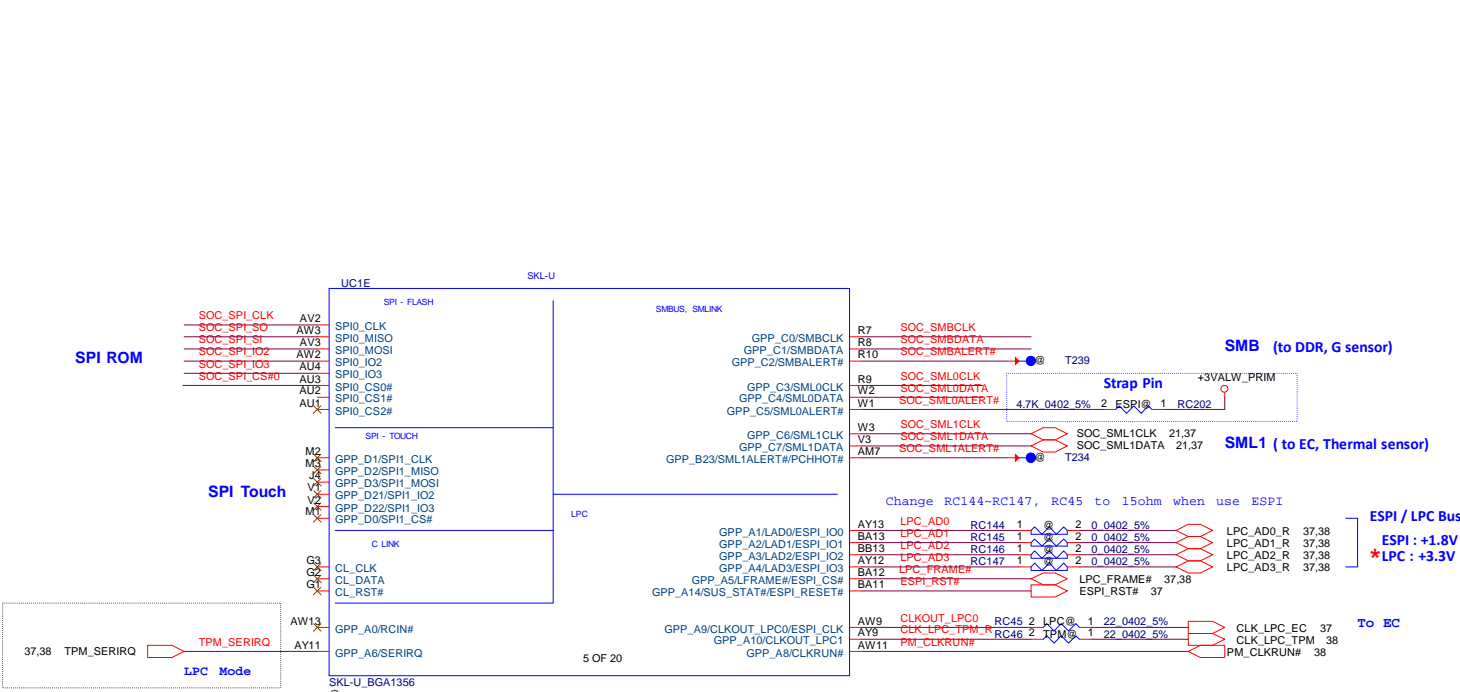
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UC1 HDCP2.2 CPU\_KBL\_H0\_i7-7500U\_2.7G SR2ZV@ SA0000A34L0

Intel DOC: 549352

3. RCOMP[0] value for SDP is 200+/-1% ohm, and for DDP is 121+/- 1% ohm

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**SML0ALERT# / GPP\_C5 (Internal Pull Down):**  
(Sampled: Rising edge of RSMRST# )

**eSPI or LPC**  
\* 0 = LPC is selected for EC --> For KB9022/9032 Use  
1 = eSPI is selected for EC --> For KB9032 Only.

**SMBALERT# / GPP\_C2 (Internal Pull Down):**  
(Sampled: Rising edge of RSMRST# )

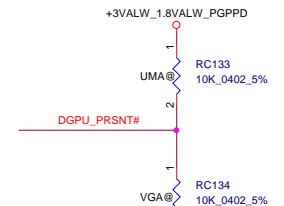
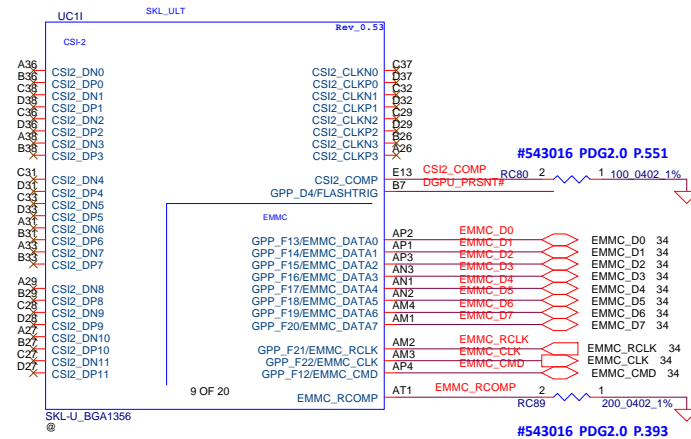
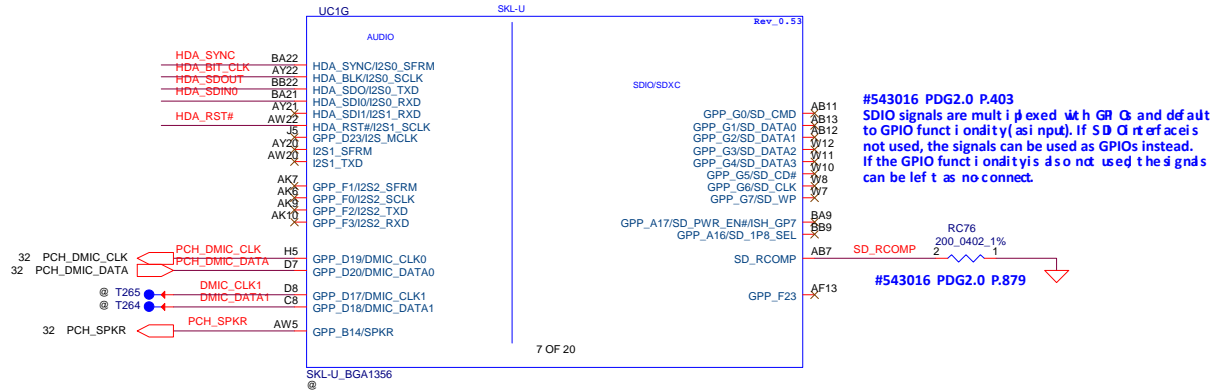
**TLS Confidentiality**  
\* 0 = Disable Intel ME Crypto Transport Layer Security (TLS) cipher suite (no confidentiality)  
1 = Enable Intel ME Crypto (TLS) (with confidentiality).  
Must be pulled up to support Intel AMT with TLS and Intel SBA (Small Business Advantage) with TLS.

Timing diagram showing the relationship between HDA\_SDI0 and ME\_EN signals. The diagram includes the following signals and their timing parameters:

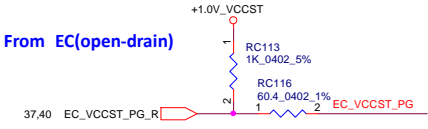
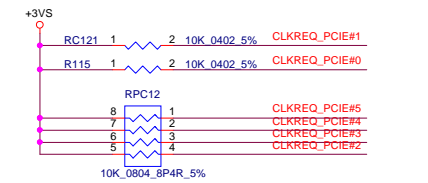
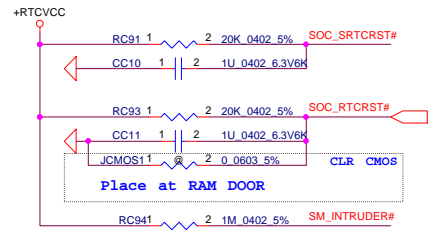
- HDA\_SDI0**: High-frequency signal with four channels (1, 2, 3, 4) and a 5% duty cycle.
- ME\_EN**: Low-frequency signal with a 5% duty cycle.
- HDA\_BIT\_CLK**: Signal with a period of 33.0804 μs and a 5% duty cycle.
- HDA\_SYNC**: Signal with a period of 33.0804 μs and a 5% duty cycle.
- HDA\_SDOUT**: Signal with a period of 33.0804 μs and a 5% duty cycle.
- HDA\_RST#**: Signal with a period of 33.0804 μs and a 5% duty cycle.

**SPKR / GPP\_B14 (Internal Pull Down):**  
(Sampled: Rising edge of PCH\_PWROK)

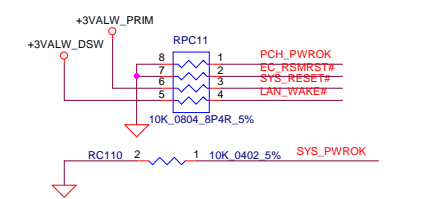
- > Two SDI signals to support two external codecs.
- > Drivers variable frequency (5MHz to 24MHz) BCLK to support:
  - SDO double pumped up to 48 Mb/s
  - SDI's single pumped up to 24 Mb/s
- > Provides cadence for 44.1 kHz based sample rate output.
- > Support 1.5V, 1.8V, and 3.3V modes.



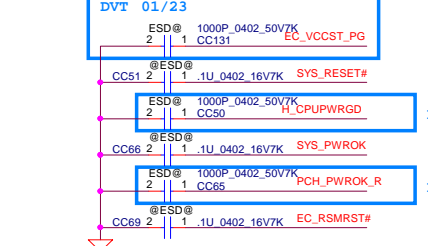
	DGPU_PRSENT#
DIS,Optimus	0
UMA	1



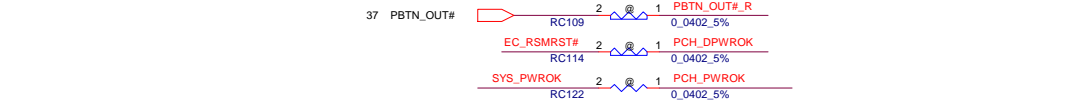
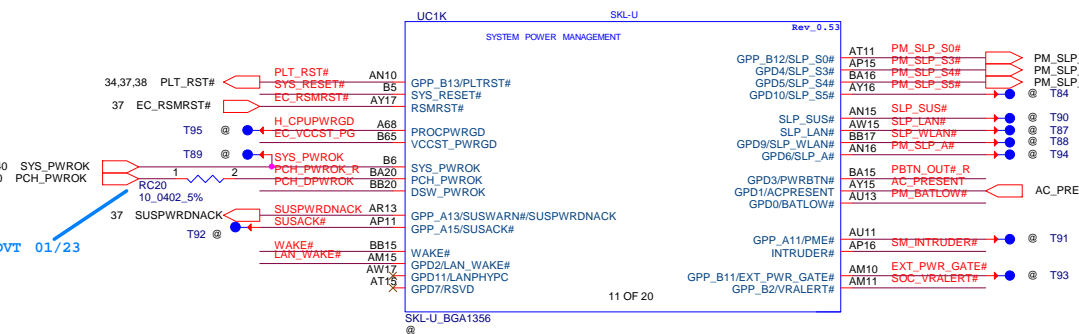
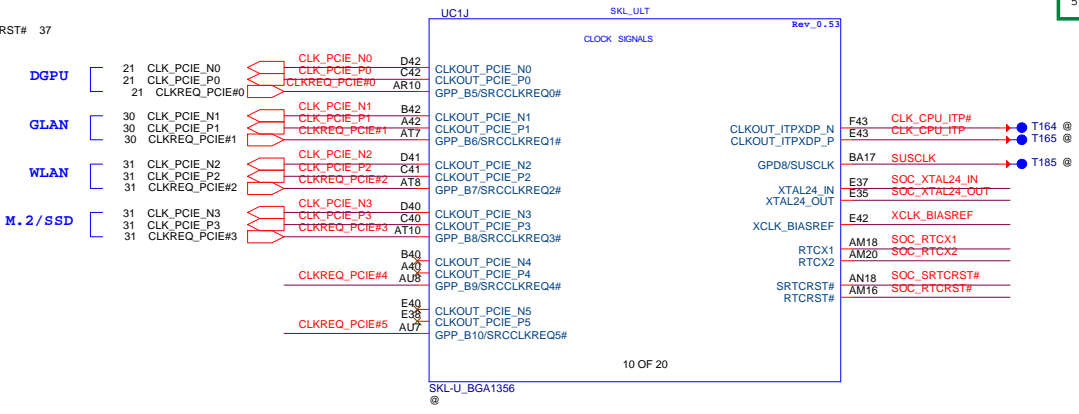
**Note for VCCST\_PWRGD**  
 1. 1.0V tolerance  
 2. PDG2.0 P.598 Figure43-5 note17: when failure events, VCCST\_PWRGD and PCH\_PWROK de-assert at the same time



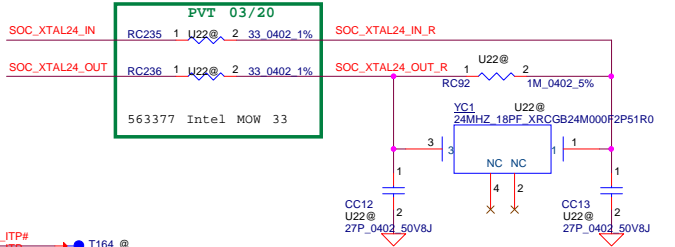
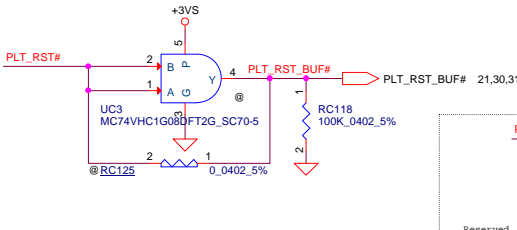
**WAKE# (DSX wake event)**  
 10K pull-up to VccDS\_W3\_3  
 The pull-up is required even if PCIe\* interface is not used on the platform



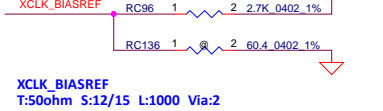
#543016 PDG2.0 P.599  
 PROCPWRGD is used only for power sequence debug and is not required to be connected to anything on the platform



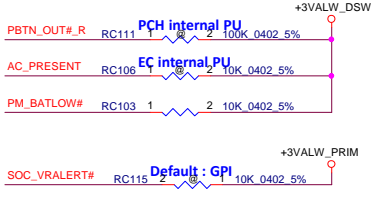
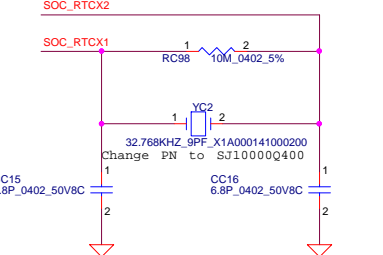
### PCH PLTRST Buffer



Follow 2014MOW48  
 Skylake U PU 2.7k ohm to 1V  
 Cannonlake U PD 60.4 ohm



2014MOW48:  
 Skylake-U use 24M 50 ohm ESR  
 Cannonlake U use 38.4M 30 ohm ESR



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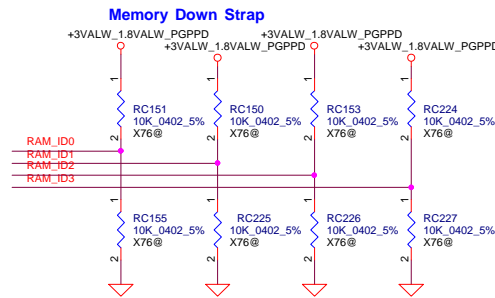
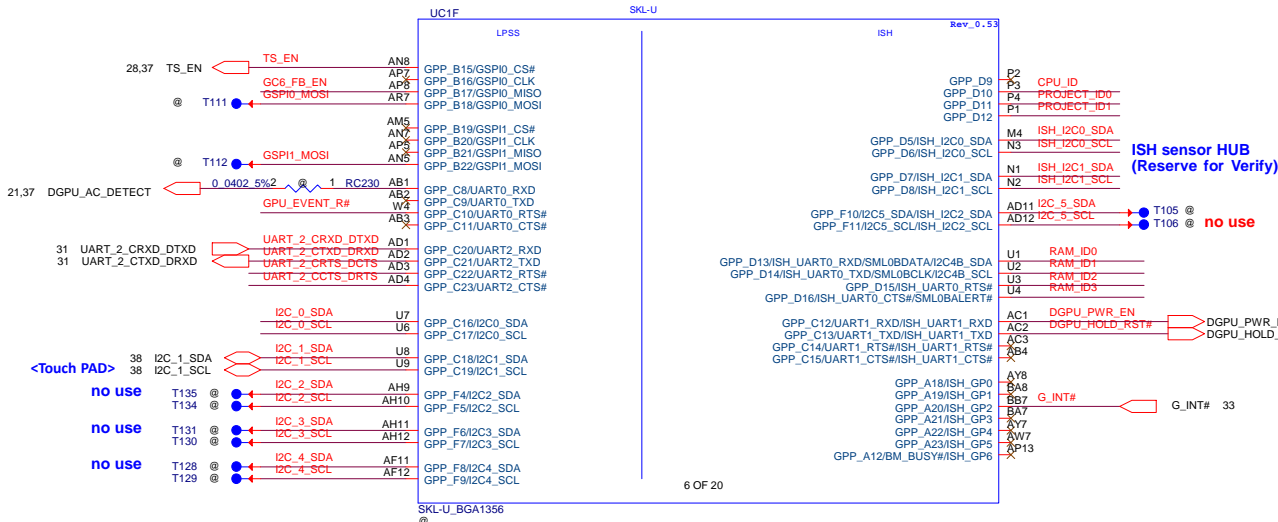
### Functional Strap Definitions

**GSPI0\_MOSI /GPP\_B18 (Internal Pull Down):**  
(Rising edge of PCH\_PWROK)  
No Reboot

- \*0 = Disable No Reboot mode. --> AAX05 Use
- 1 = Enable No Reboot mode. (PCH will disable the TCO Timer system reboot feature). This function is useful when running ITP/XDP.

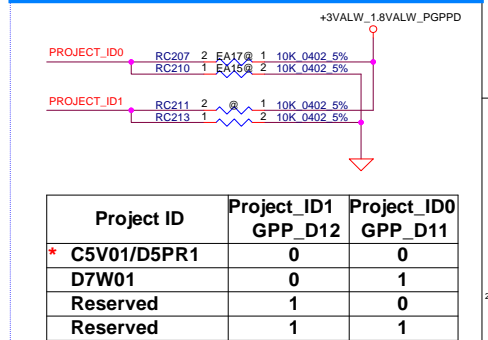
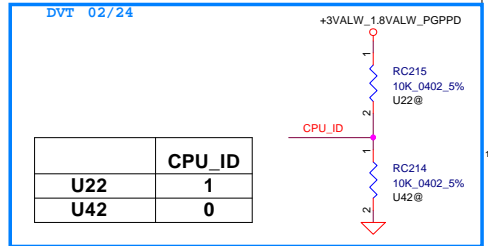
**GSPI1\_MOSI / GPP\_B22 (Internal Pull Down):**  
(Rising edge of PCH\_PWROK)

- Boot BIOS Strap Bit
- \*0 = SPI Mode --> AAX05 Use
- 1 = LPC Mode

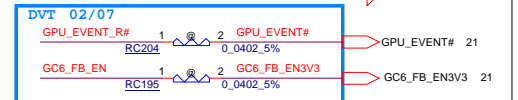
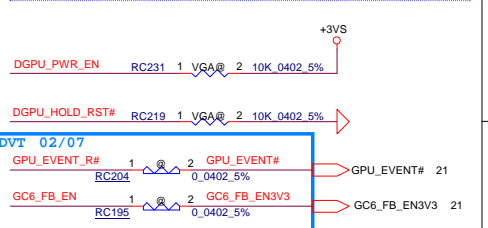
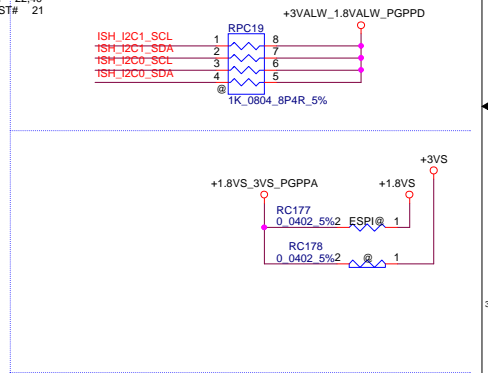


ZZZ	Hynix4GB	X76739BOL02
ZZZ	Micron4GB	X76739BOL03
ZZZ	Samsung4GB	X76739BOL01

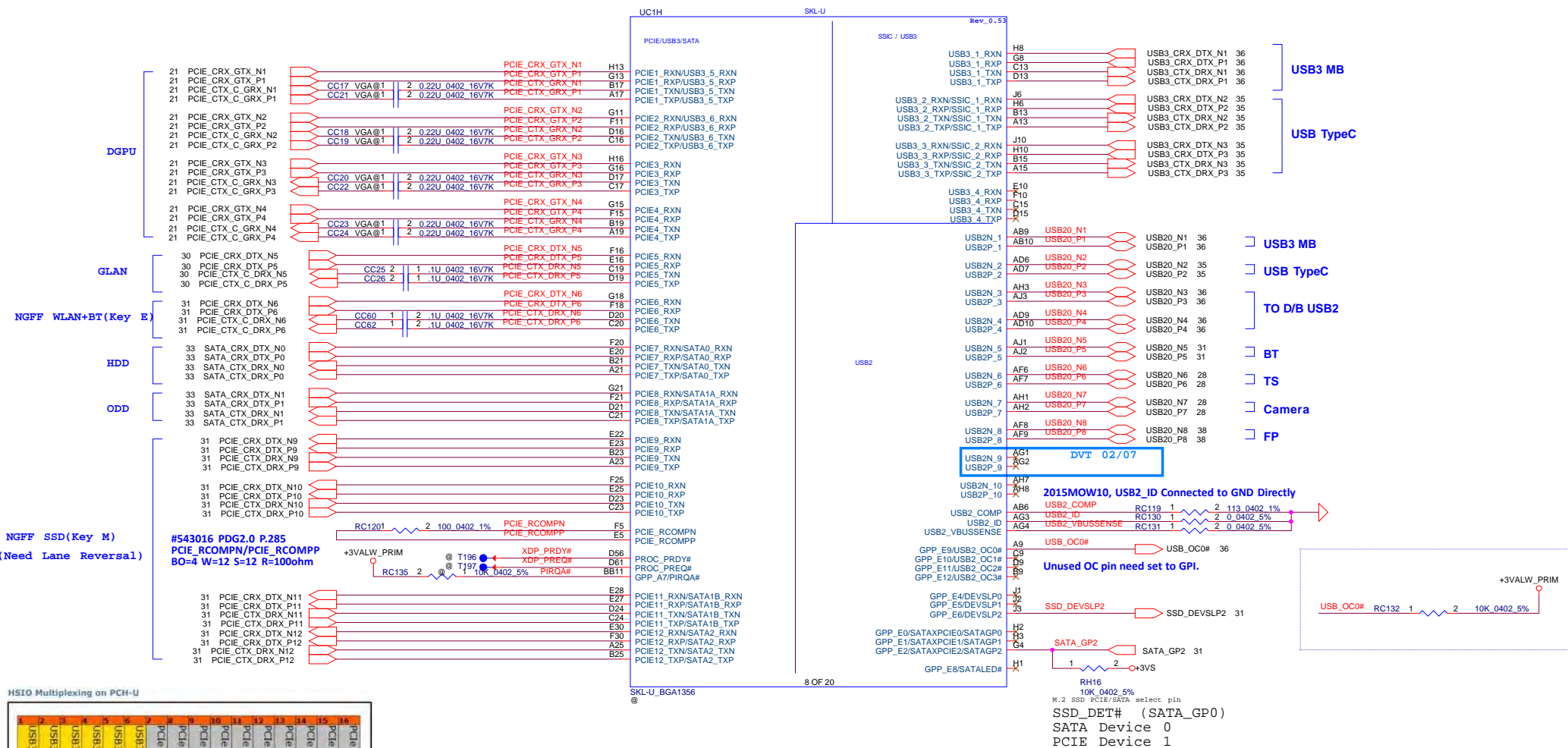
	RAM_ID3	RAM_ID2	*RAM_ID1	*RAM_ID0	PartNumber - Description
Hynix 4GB	0	0	0	0	SA0000A1H20 (S IC D4 512M16 H5AN8G6NAFHR-UHC FBGA ABOI)
Micron 4GB	0	0	0	1	SA00009V220 (S IC D4 512M16 MT40A512M16Y-083E:B ABOI)
Samsung 4GB	0	0	1	0	SA00009U420 (S IC D4 512M16 K4A8G16SWB-BCRC FBGA 96P ABO I)
	0	0	1	1	
No OnBoard Memory	1	1	1	1	No On Board Memory



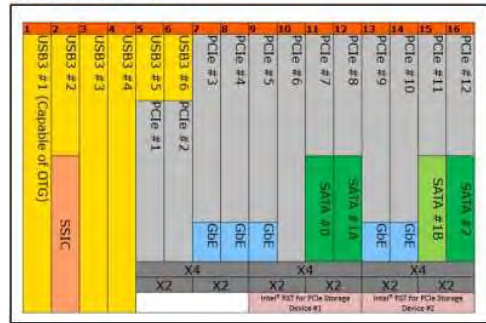
Project ID	Project_ID1 GPP_D12	Project_ID0 GPP_D11
* C5V01/D5PR1	0	0
D7W01	0	1
Reserved	1	0
Reserved	1	1



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		Size	Document Number
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HSIO Multiplexing on PCH-U



PCH-LP Details		PCIe* Controller #1				PCIe* Controller #2				PCIe* Controller #3			
Flex I/O Lane #	PCIe* Lane #	5	6	7	8	9	10	11	12	13	14	15	16
Base-U	1x4	RP1	RP3	RP5	RP7	RP9	RP11	RP13	RP15	RP17	RP19	RP21	RP23
	2x2	RP1	RP3	RP5	RP7	RP9	RP11	RP13	RP15	RP17	RP19	RP21	RP23
	1x2+2x1	RP1	RP3	RP5	RP7	RP9	RP11	RP13	RP15	RP17	RP19	RP21	RP23
	2x2+2x2	RP1	RP3	RP5	RP7	RP9	RP11	RP13	RP15	RP17	RP19	RP21	RP23
Premium-U	1x4	RP1	RP3	RP5	RP7	RP9	RP11	RP13	RP15	RP17	RP19	RP21	RP23
	2x2	RP1	RP3	RP5	RP7	RP9	RP11	RP13	RP15	RP17	RP19	RP21	RP23
	1x2+2x1	RP1	RP3	RP5	RP7	RP9	RP11	RP13	RP15	RP17	RP19	RP21	RP23
	2x2+2x2	RP1	RP3	RP5	RP7	RP9	RP11	RP13	RP15	RP17	RP19	RP21	RP23

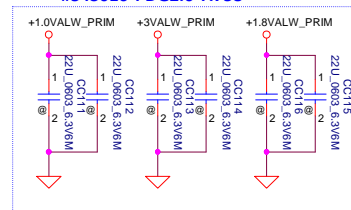
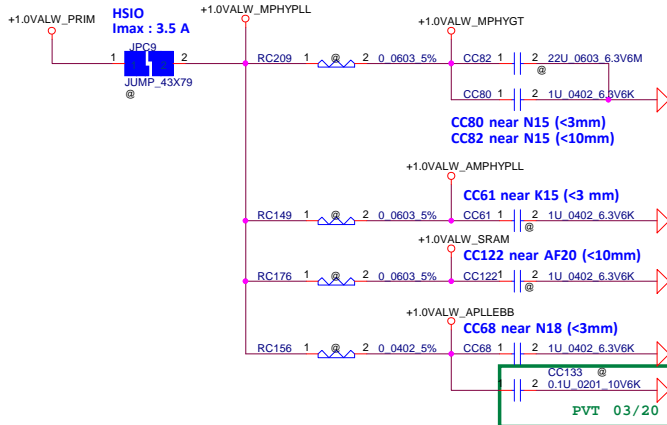
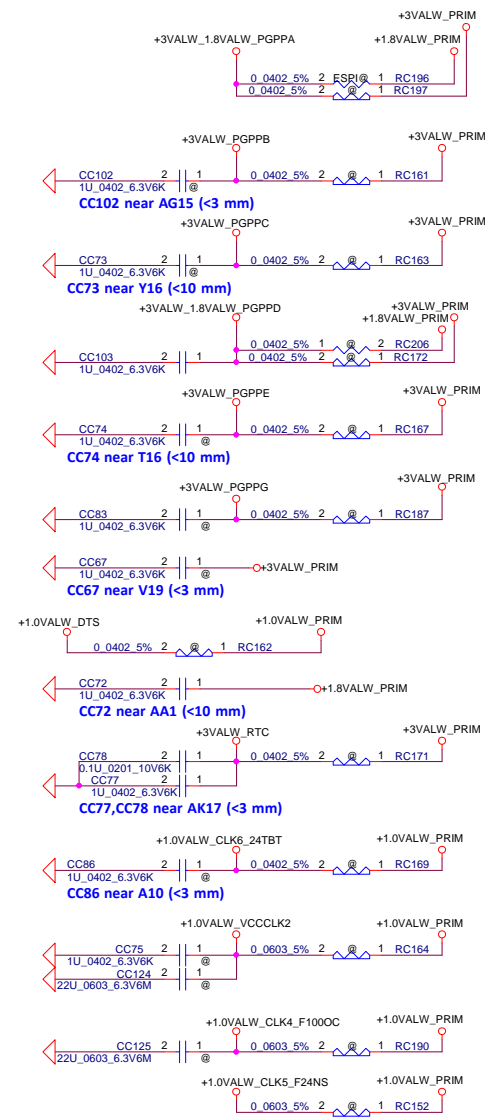
GPIO	DEVICE CONTROL
USB_OC0#	USB2 Port 1
USB_OC1#	NA
USB_OC2#	NA
USB_OC3#	NA
DEVSLP0	NA
DEVSLP1	NA
DEVSLP2	NA
SATA_GP0	NA
SATA_GP1	NA
SATA_GP2	NA

**DEVSLP[2:0] Implementation**  
DEVSLP is a host-controlled hardware signal which enables a SATA host and device to enter an ultra-low interface power state, including the possibility to completely power down host and device PHYs.  
The processor provides three SATA DEVSLP signals, DEVSLP[2:0] for SKL-U.  
• When high DEVSLP requests the SATA device to enter into the DEVSLP power state  
• When low DEVSLP requests the SATA device to exit from the DEVSLP power state and transition to active state.

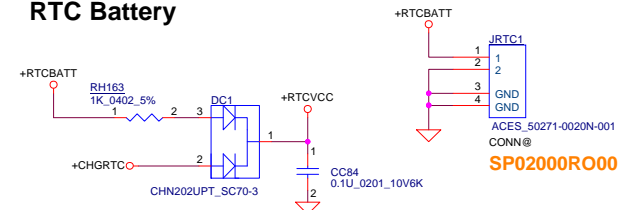
**SATA General Purpose (SATAGP[2:0]) Signals**  
• The process or provides three SATA general purpose input signals SATAGP[2:0] for SKL-U. These signals can be configured as interlock switch inputs corresponding to a given SATA port.  
• When used as an interlock switch status input on this signal should be driven to 0 to indicate that the switch is closed and to 1 to indicate that the switch is open.  
If mechanical presence switches will not be used on the platform SATAGP[2:0] signals can be configured as GPP\_E[2:0] GPIOs signals.

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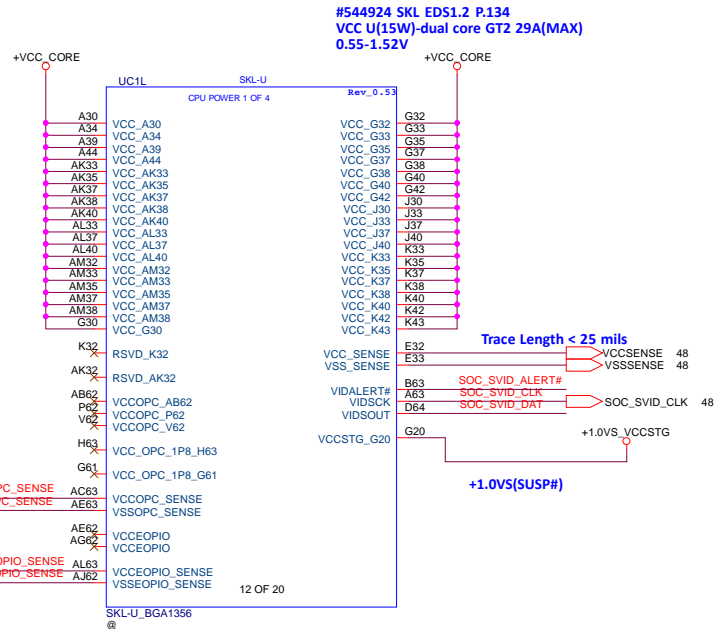




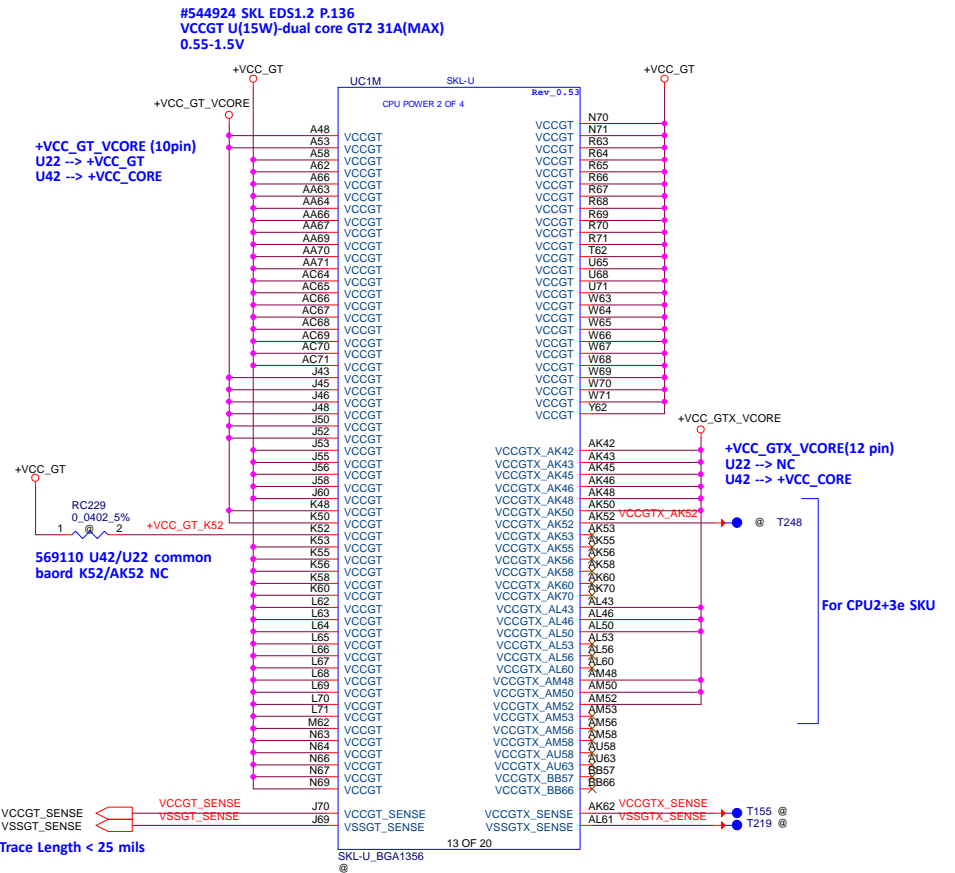
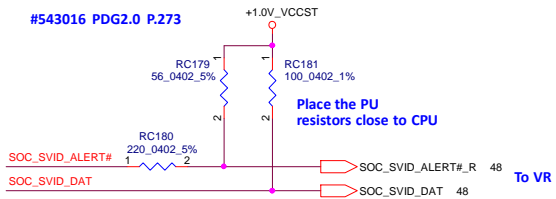
Power Rail	Voltage
+CHGRTC	3.383V(MAX)
BAT54C(VF)	240 mV
+RTCVCC	3.143V
Result : Pass	



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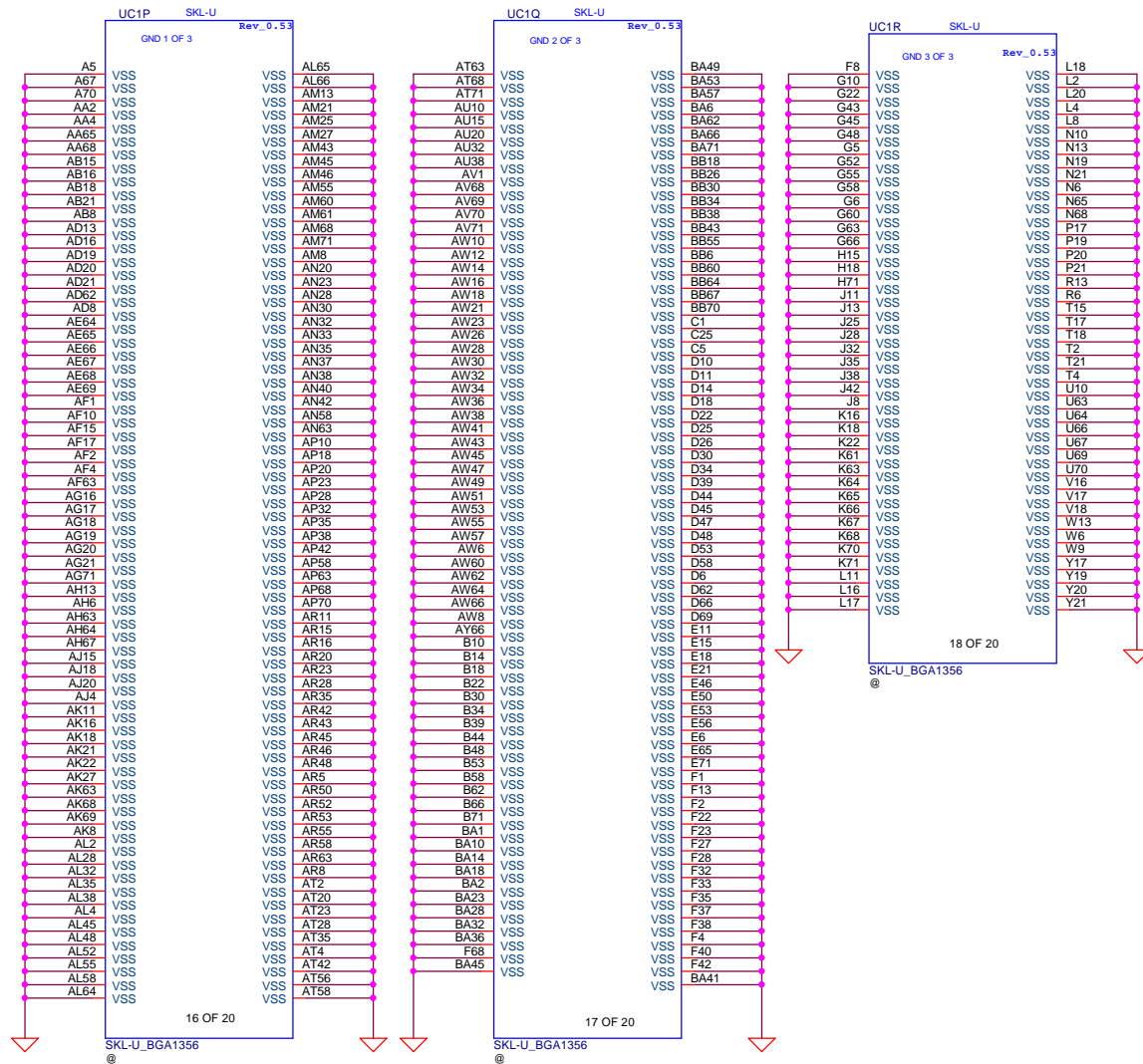


#543016 PDG2.0 P.273



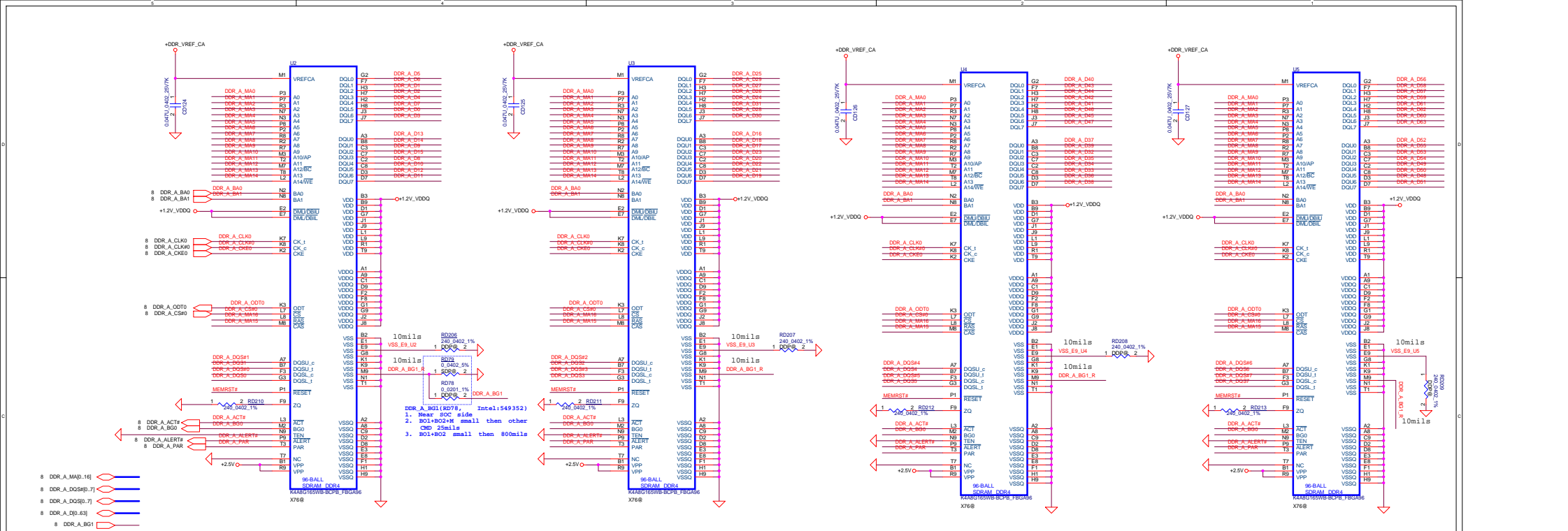
Processor Power Rails

Power Rail	Description	Control
VCC	Processor IA Cores Power Rail	SVID
VCCGT	Processor Graphics Power Rails	SVID
VCCGTx	Processor Graphics Extended Power Rail Available only for GT3/GT4 processor SKUs	SVID
VCCSA	System Agent Power Rail	SVID/Fixed (SKU dependent)
VCCID	ID Power Rail	Fixed
VCCST	Sustain Power Rail	Fixed
VCCPLL	Processor PLLs power rail	Fixed
VDDQ	Integrated Memory Controller Power Rail	Fixed (Memory technology dependent)
VCCOPC	Processor OPC power rail (available only in SKU's with OPC)	Fixed
VCCOPC_1P8	Processor OPC power rail (available only in SKU's with OPC)	Fixed
VCCEOPIO	Processor EOPIO power rail (available only in SKU's with OPC)	Fixed

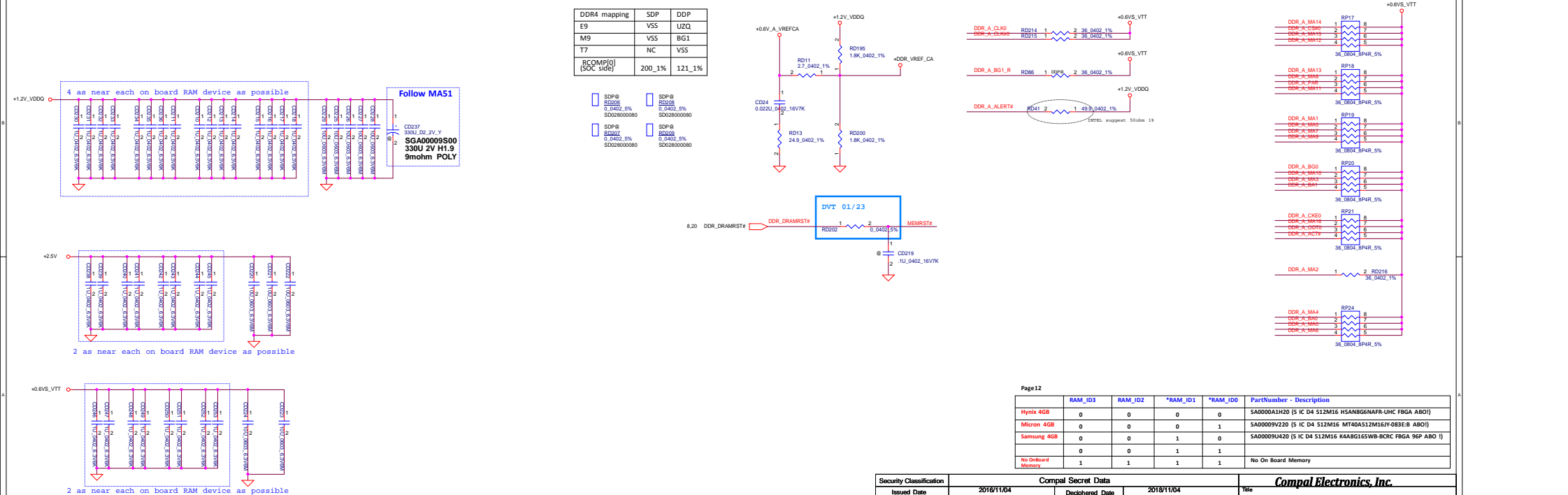


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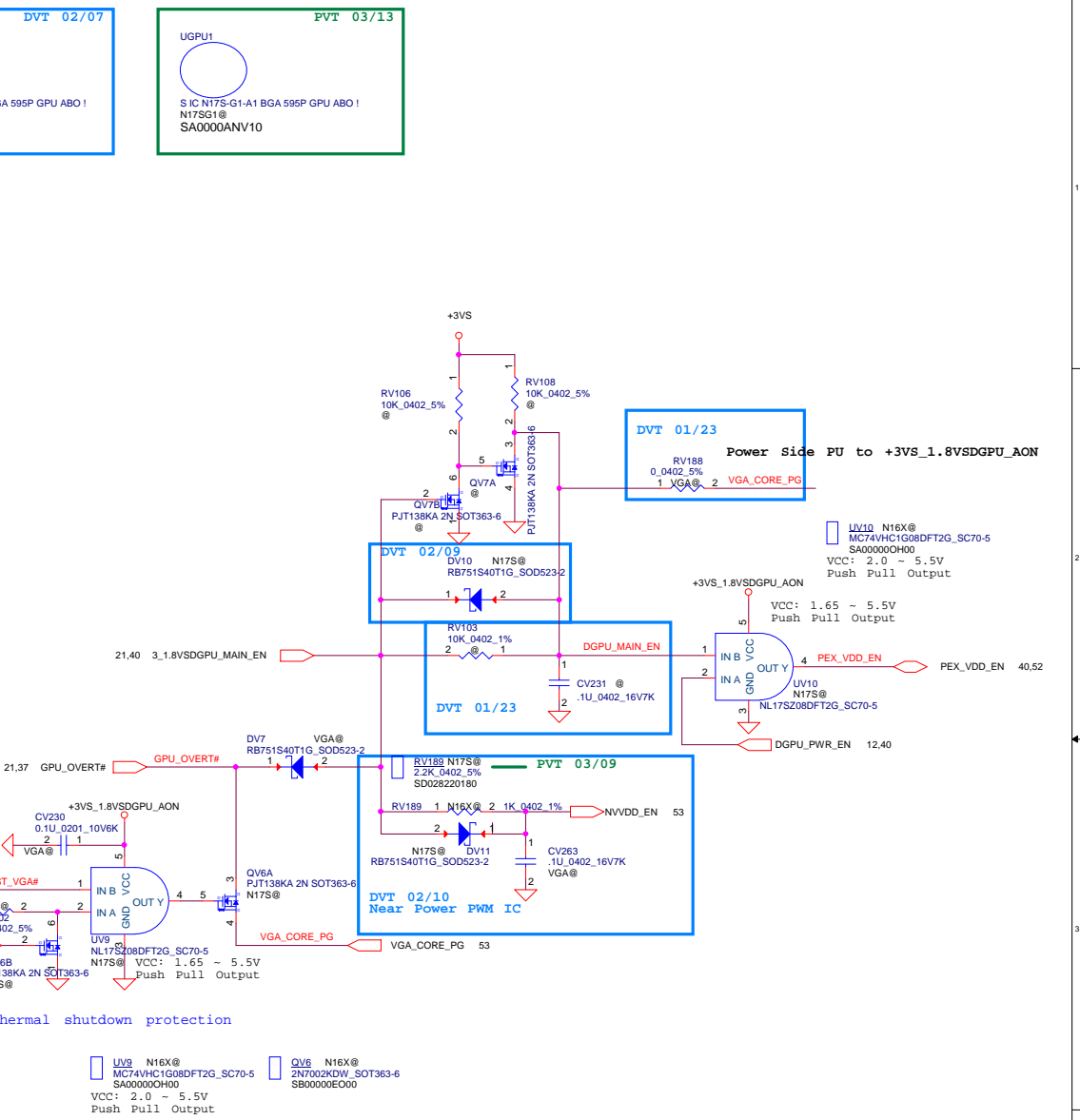
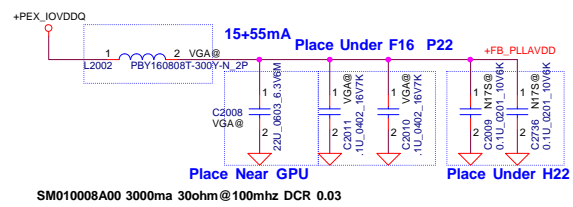
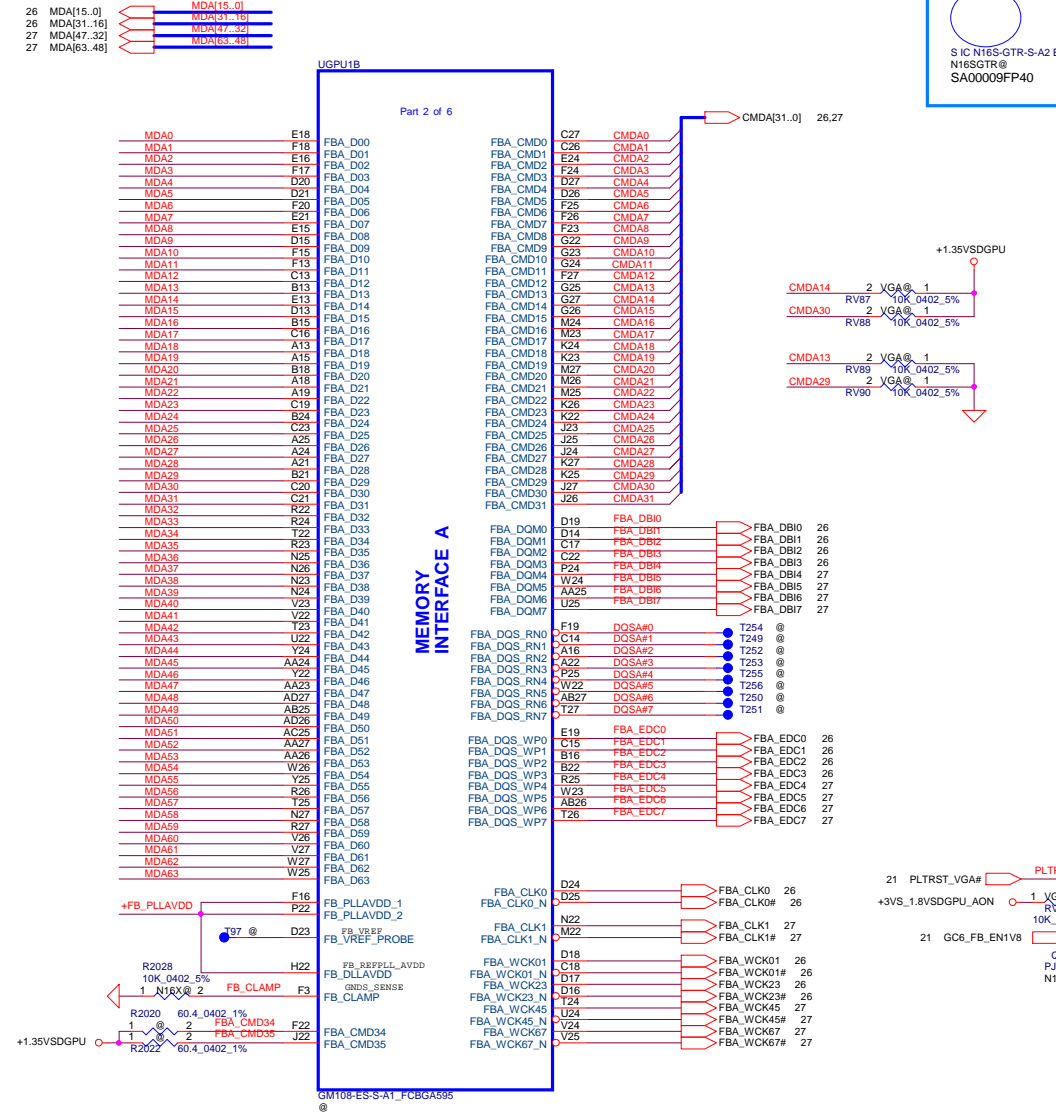
# TERMINATION



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VRAM Interface

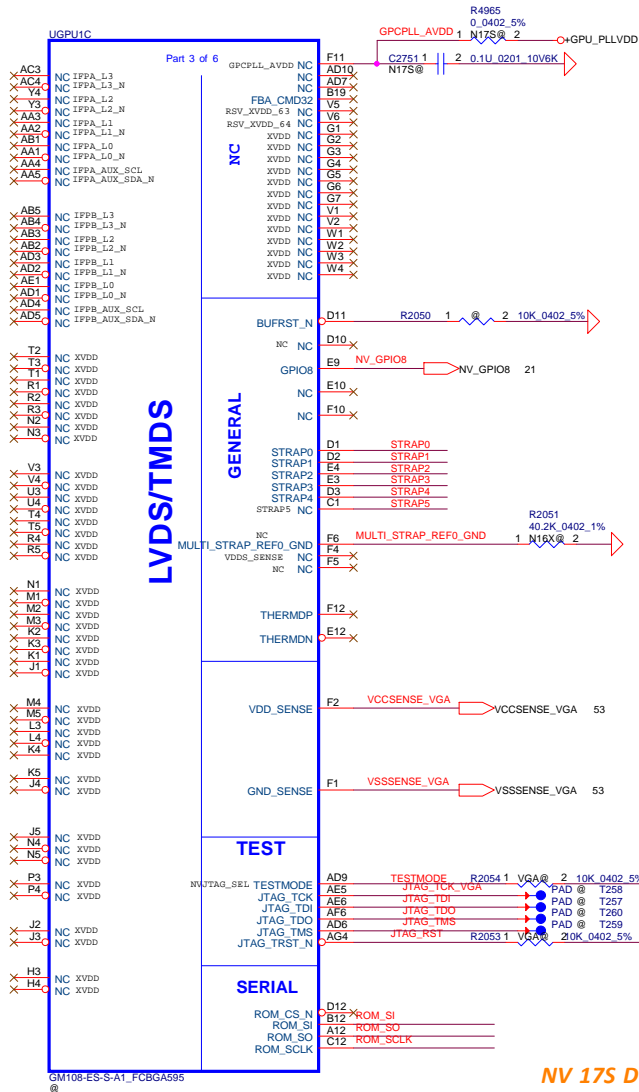


DA-08329-001 V01 Table 5. Frame Buffer PLLs Decoupling and Filtering

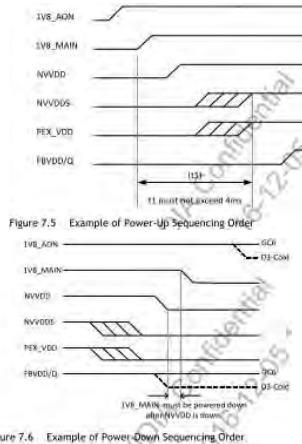
GPU	Capacitor Type	Population		
		Footprint	N16	N17
GB2B-64, GB2C-64	0.1 μF	X7R 0402	2	4
	22 μF	X6S 0805	1	1
	30 Ω (ESR<0.010 Ω)	0603	1	1

NV 15x DG-06803-V03  
NV 16x DG-07158-V04

GPU Package	Rail	Capacitor Type	Footprint	Population	Location
GB2B-64	FBX_PLL_AVDD and FB_DLL_AVDD Combined	0.1 μF	X7R 0402	2	Under GPU
		22 μF	X5R 0805	1	Near GPU
		Bead Type			
		30 Ω (ESR<0.010 Ω)		0603	1



### NV 17S DG-07785-001\_V07



### NV 16x DG-07158-V05

Table 3-4. GPU Core Sensing Line Routing Constraints

Constraint Parameter	Requirement
Single-ended Impedance	25 Ω ± 10%
Differential Trace Impedance	50 Ω ± 15%
Reference Plane	GND Reference
Routing Type	Stripline <sup>1</sup> or Microstrip
Dielectric spacing	Stripline: ≥ 3.0x dielectric Microstrip: ≥ 4.0x dielectric
Intrapair skew	≤ 5 ps
Via stub	
Trace length	GPU to R <sub>0</sub> /R <sub>0</sub> ≤ 250 mm (9842.5 mil) R <sub>0</sub> /R <sub>0</sub> to VR ≤ 50 mm (1968.5 mil)

Note:  
1. Stripline is recommended to minimize EMI. Do not route over any voids.

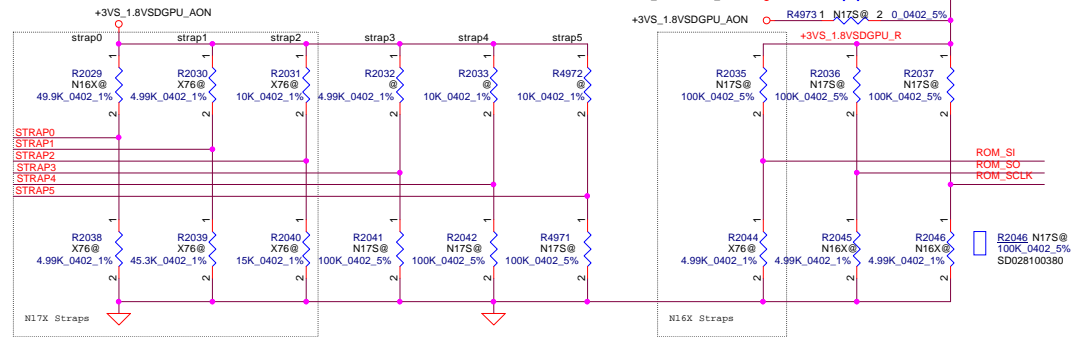
Table 15-2. Resistance Mapping to Hex Values

Resistor Values	Pull-Up to 3V3_MAIN	Pull-Down to GND
4.99 kΩ	1000	0000
10.0 kΩ	1001	0001
15.0 kΩ	1010	0010
20.0 kΩ	1011	0011
24.9 kΩ	1100	0100
30.1 kΩ	1101	0101
34.8 kΩ	1110	0110
45.3 kΩ	1111	0111

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### MULTI LEVEL STRAPS



Multi strap table

GPU	VRAM Voltage	RANK	X76	Freq	Memory Size	Memory Config	strap0	strap1	strap2	strap3	strap4	strap5	ROM_SI	ROM_SO	ROM_SCLK
N16S-GTR	+1.35V			2.5GHz	128Mx32x2 1G	0x7 (SA00009TT30) Samsung K4G41325FE-HC28 0x6 (SA000085V70) Hynix H5GC4H24AJR-T2C 0x3 (SA00007D880) Samsung K4G41325FC-HC03 0x4 () Micron	PU 49.9K	NC	NC	NC	NC	NC	PD 45.3K PD 34.8K PD 20K PD 24.9K	PD 4.99K	PD 4.99K
			X76739BOL04		256Mx32x2 2G	0x0 (SA000094R30) Samsung K4G80325FB-HC03 0x5(SA00009ZG20) Hynix H5GC8H24MJR-T2C 0x1 (SA000096K30) Micron MT51J256M32HF-60-A							PD 4.99K PD 30.1K PD 10K		

Decive ID : N16S-GTR 0x134D

Multi strap table

GPU	VRAM Voltage	RANK	X76	Freq	Memory Size	Memory Config	strap0	strap1	strap2	strap3	strap4	strap5	ROM_SI	ROM_SO	ROM_SCLK
N17S-G1	+1.35V			3.0GHz	128Mx32x2 1G	0x7 (SA00009TT30) Samsung K4G41325FE-HC28 0x6 (SA00008HQ10) Hynix H5GC4H24AJR-ROC 0x8 (SA00009E300) Micron EDW4032BAG-70-F-R	PU 100K	PU 100K	PU 100K						
			X76739BOL07		256Mx32x2 2G	0x0 (SA000092D00) Samsung K4G80325FB-HC28 0x2 (SA00009U110) Hynix H5GC8H24MJR-ROC 0x1 (SA00009TY10) Micron MT51J256M32HF-70-A	PD 100K	PD 100K	PD 100K				PU 100K	PU 100K	PU 100K PD 100K

Decive ID : N17S-G1-A1 0x1D10

### DA-08329-001\_V02

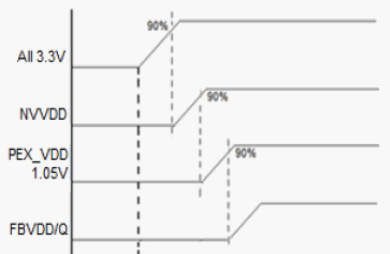
Table 8. Other PLLs Power Decoupling and Filtering

GPU	Type	Footprint	Population	N16	N17	Location
PLLVD0 (N17: X5_PLLVD0) Supply Rail						
GR2B-64, GRC-64	0.1 µF X7R 0402	1	1			Under GPU
	22 µF XSR 0805	1	0			Near GPU
	Bead Type: L2=30 Ω (ESR=0.05 Ω)					
SP_PLLVD0 and VID_PLLVD0 Combined Supply Rails						
GR2B-64, GRC-64	0.1 µF X7R 0402	2	2			Under GPU
	10 µF XSR 0603	1	0			Near GPU
	47 µF XSR 0805	1	0			Near GPU
	Bead Type: L2=300 Ω (ESR=0.2 Ω)					
NC (N17: GPCPLL_AVDD) Supply Rail						
GR2C-64	0.1 µF X7R 0402	N/A	1			Under GPU
	4.7 µF X5S 0603	N/A	1			Near GPU
	22 µF X5S 0805	N/A	1			Near GPU
	Bead Type: L2=30 Ω (ESR=0.010 Ω)					
	0.603	N/A	1			Near GPU

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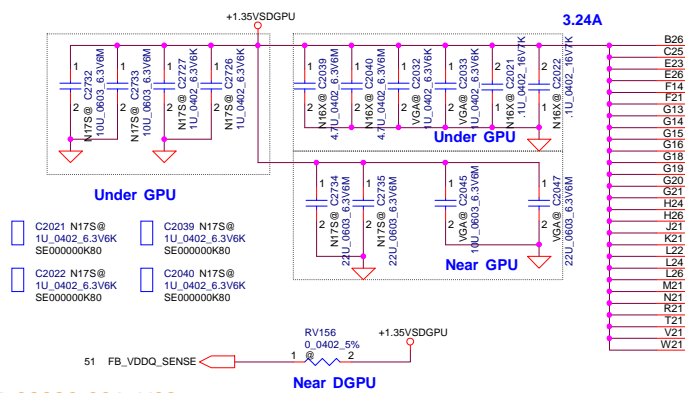
### VGA Power Sequence (N16X)



Notes: - All 3.3V includes all rails powered at 3.3V  
- PEX\_VDD 1.05V includes all rails that are shared

Table 3-9. DDR3 GPU-Side FBVDD and FBVDDQ Combined Decoupling

GPU Package Type	Capacitor Type		Footprint		Population	Location
GB28-64/GB2-64 DDR3	0.1 $\mu$ F	X7R	0402	2	2	Under GPU
	1 $\mu$ F	X7R	0603	2	2	Under GPU
	4.7 $\mu$ F	X6S	0603	2	2	Under GPU
	10 $\mu$ F	X5R	0805	1	1	Near GPU
	22 $\mu$ F	X5R	0805	1	1	Near GPU



## Table 4. Frame Buffer Core and IO Decoupling and Filtering

GPU	Capacitor Type	Footprint	Population		Location	
			N16	N17		
FBVDD/Q Supply Rail for GDDR5						
GB28-64, GB2C-64	0.1 $\mu$ F	X7R	D402	2	0	Under GPU
	1 $\mu$ F	X7R	D603	2	8	Under GPU
	4.7 $\mu$ F	X6S	D603	2	0	Under GPU
	10 $\mu$ F	X6S	D603	0	2	Under GPU
	10 $\mu$ F	X6S	D603	1	1	Hear GPU
	22 $\mu$ F	X6S	D603W	1	3	Hear GPU

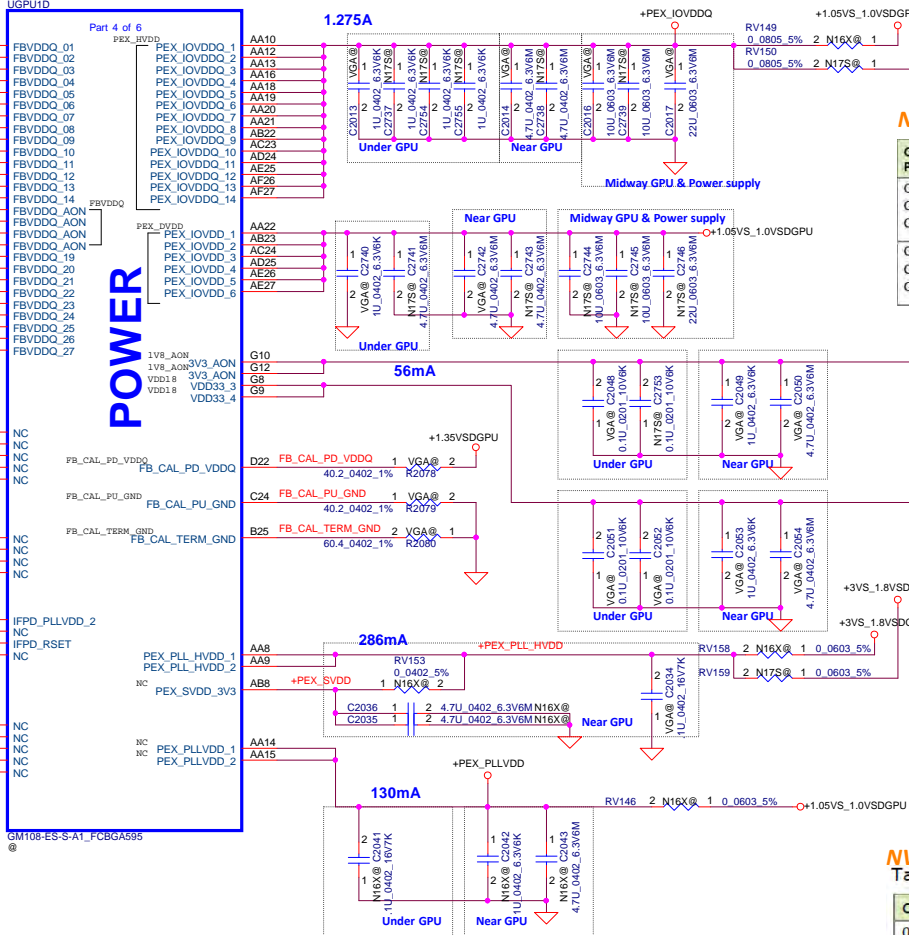


Table 3-16. PEX\_IOVDD/Q Power Rail Combined

GPU Package Type	Capacitor Type		Footprint	Population	Location
GB2B-64/ GB2-64	1.0 $\mu$ F	X6S	0402	1	Under GPU
	4.7 $\mu$ F	X6S	0603	1	Near GPU
	10 $\mu$ F	X5R	0805	1	Midway between GPU and Power Supply
	22 $\mu$ F	X5R	0805	1	Midway between GPU and Power Supply

## Table 7-13. Default GPU Drive Calibration for Frame Buffer Interface

Memory/PKG	FBVDDQ	FBCAL_PU_GND	FBCAL_PD_VDDQ	FBCAL_TERM_GND
GDDR5A BGA-170	1.35 V or 1.50 V	40.2 $\Omega$	40.2 $\Omega$	60.4 $\Omega$

GPU Package	Rail	Capacitor Type	Footprint	Population	Location	
GB2Z-64	3V3_MAIN	0.1 $\mu$ F	X6S 0402	2	2	Under GPU
GB4B-128		1 $\mu$ F	X5R 0603	1	1	Near GPU
GB3-256		4.7 $\mu$ F	X5R 0603	1	1	Near GPU
GB2B-64	3V3_AON	0.1 $\mu$ F	X6S 0402	1	1	Under GPU
GB4B-128		1 $\mu$ F	X5R 0603	1	1	Near GPU
GB3-256		4.7 $\mu$ F	X5R 0603	1	1	Near GPU

## Table 9. VDD ADN and VDD\_MAIN Decoupling.

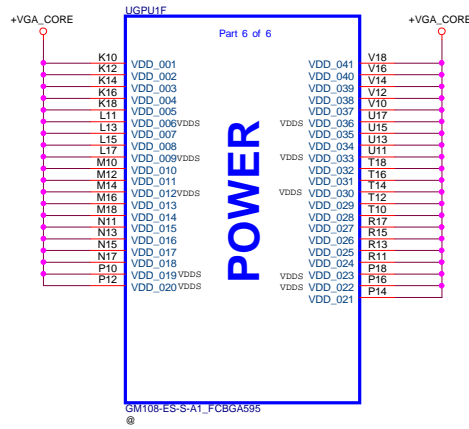
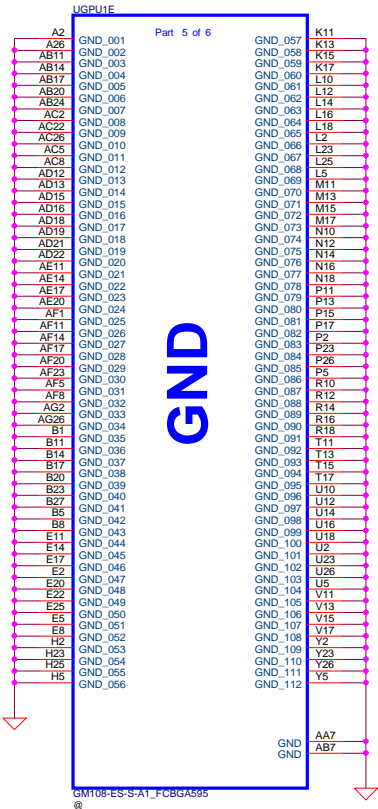
GPU	Capacitor Type	Footprint	Population		
			N16	N17	Location
<b>N16 JV3_AAH (N17 VD016) Supply Rail</b>					
GB23-64	1.0 $\mu$ F	3078	0	2	Under GPU
GB7C-64	1.0 $\mu$ F	3555	0	1	Near GPU
	4.7 $\mu$ F	3565	0	1	Near GPU
<b>N16 JV3_AOH (N17 YFV_AOH) Supply Rail</b>					
GB28-64	0.1 $\mu$ F	3278	1	2	Under GPU
GB2C-64	1.0 $\mu$ F	3565	0	1	Near GPU
	4.7 $\mu$ F	3565	0	1	Near GPU

Table 3-18. PEX\_SVDD\_3V3 and PEX\_PLL\_HVDD Decoupling

Capacitor Type		Footprint	Population	Location
0.1 $\mu$ F	X7R	0402	1	Near GPU
4.7 $\mu$ F	X5R	0603	2	Near GPU

## Table 3-17. PEX\_PLLVDD Decoupling

Capacitor Type		Footprint	Population	Location
0.1 $\mu$ F	X7R	0402	1	Under GPU
1.0 $\mu$ F	X5R	0603	1	Near GPU
4.7 $\mu$ F	X5R	0805	1	Near GPU



# NV 16x DG-07158-V05 Table 3-6. NVVDD Decoupling Footprint and Population

GPU Package Type	Capacitor Type	Footprint	Population	Location	Comments
GB2B-64 / GB2-64	4.7 $\mu$ F	X6S 0603	10	10	Under GPU
	1 $\mu$ F	X6S 0402	4	4	Under GPU
	47 $\mu$ F	X5R 0805	1	1	Near GPU
	22 $\mu$ F	X5R 0805	1	1	Near GPU
	4.7 $\mu$ F	X5R 0805	5	5	Near GPU
	330 $\mu$ F	POS 7343	1	1	Near GPU ESR $\leq$ 6 m $\Omega$

## DA-07750-000-V02

Table 6. EDP-Continuous<sup>3</sup>

Products	VRAM Type	GPU Core		GPU FBIO		FB Total <sup>1,5</sup>		1.05V Total <sup>2</sup>		3.3V Total	
		(A)	(A)	(A)	(A)	(A)	(A)	(A)	(A)	(A)	(A)
N16S-GMR	GDDR5	19.0	2.0	—	4.2	0.80	0.06				
	DDR3/L	21.0	1.4	1.4	2.4	2.3	0.80	0.06			
N16S-GTR	GDDR5 @ 2.0 GHz	26.5	—	2.0	—	4.2	0.80	0.06			
	GDDR5 @ 2.5 GHz	26.5	—	2.0	—	4.7	0.80	0.06			
	DDR3/L	26.0	1.4	1.4	2.4	2.3	0.80	0.06			

Table 7. EDP-Peak<sup>3</sup>

Products	VRAM Type	GPU Core		GPU FBIO		FB Total <sup>1,5</sup>		1.05V Total <sup>2</sup>	
		(A)	(A)	(A)	(A)	(A)	(A)	(A)	(A)
N16S-GMR	GDDR5	34.0	—	2.9	—	6.8	2.1		
	DDR3/L	39.5	2.6	2.3	4.1	3.9	2.1		
N16S-GTR	GDDR5 @ 2.0 GHz	53.0	—	2.9	—	6.8	2.1		
	GDDR5 @ 2.5 GHz	53.0	—	3.1	—	7.2	2.1		
	DDR3/L	51.0	2.6	2.3	4.1	3.9	2.1		

## DA-07751-000-V02

Table 5. EDP-Continuous<sup>3</sup>

Product	VRAM Type	GPU Core		GPU FBIO		FB Total <sup>1,5</sup>		1.05V Total <sup>2</sup>		3.3V Total	
		(A)	(A)	(A)	(A)	(A)	(A)	(A)	(A)	(A)	(A)
N16S-GMR1	GDDR5 @ 2.0 GHz	18.5	—	2.0	—	4.2	0.8	0.06			
	GDDR5 @ 2.5 GHz	18.5	—	2.0	—	4.7	0.8	0.06			
	DDR3/L	19.0	1.4	1.4	2.4	2.3	0.8	0.06			

Table 6. EDP-Peak<sup>3</sup>

Products	VRAM Type	GPU Core		GPU FBIO		FB Total <sup>1,5</sup>		1.05V Total <sup>2</sup>	
		(A)	(A)	(A)	(A)	(A)	(A)	(A)	(A)
N16S-GMR1	GDDR5 @ 2.0 GHz	30.0	—	2.9	—	6.8	2.1		
	GDDR5 @ 2.5 GHz	31.0	—	3.1	—	7.2	2.1		
	DDR3/L	28.5	2.6	2.3	4.1	3.9	2.1		

## SP-08318-001\_V03

Table 7. Output EDP-Continuous

Product	NVVDD	GPU FBIO	FB Total <sup>3</sup>	1.0V Total <sup>1</sup>	1.8V Total <sup>2</sup>
	(A)	(A)	(A)	(A)	(A)
N17S-G1	30.0	2.0	3.4	0.1	0.3

Table 8. Output EDP-Peak

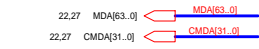
Product	NVVDD	GPU FBIO	FB TOTAL <sup>4</sup>	1.0V Total <sup>1</sup>
	(A)	(A)	(A)	(A)
N17S-G1	60.1	3.2	6.6	0.2

## DA-08329-001\_V01

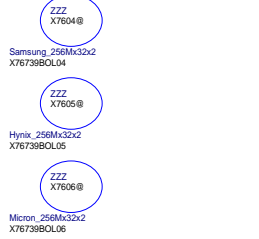
Table 3. NVVDD and NVVDDs Decoupling and Filtering

GPU	Capacitor Type	Footprint	Population		Location
			N16	N17	
NVVDD Supply Net					
GB2B-64, GB2C-64	4.7 $\mu$ F	X6S 0603	10	8	Under GPU
	1 $\mu$ F	X6S 0402	4	3	Under GPU
	47 $\mu$ F	X5R 0805	1	-	Near GPU
	10 $\mu$ F	X7R 0805	-	4	Near GPU
	22 $\mu$ F	X5R 0805	1	3	Near GPU
	4.7 $\mu$ F	X5R 0805	1	4	Near GPU
330 $\mu$ F	POS 7343	1	1	Near GPU	
NVVDDs Supply Net					
GB2C-64 Only	4.7 $\mu$ F	X6S 0603	N/A	4	Under GPU
	1 $\mu$ F	X6S 0402	N/A	2	Under GPU
	10 $\mu$ F	X6S 0805	N/A	7	Near GPU
	22 $\mu$ F	X6S 0805LP	N/A	1	Near GPU
	330 $\mu$ F	POS 7343	N/A	1	Near GPU

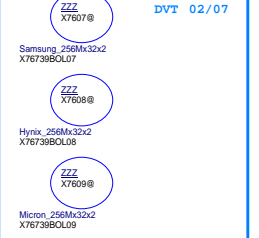
# VRAM GDDR5 chips GDDR5 Mode H Mapping



## X76 for N16X 2G VRAM

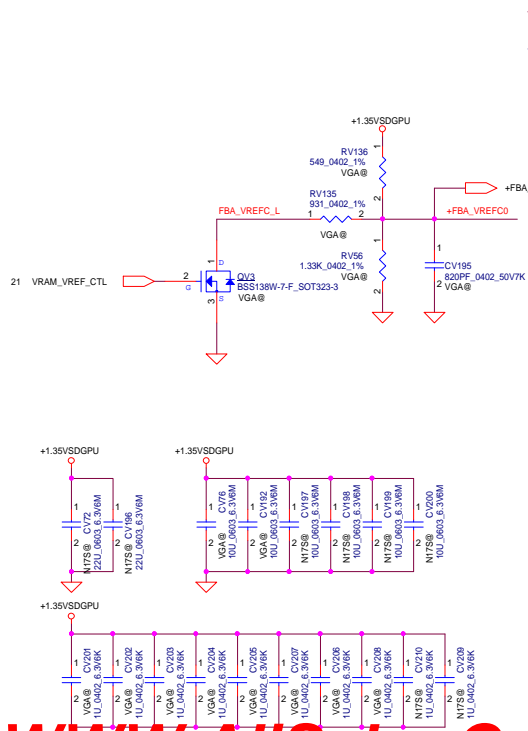
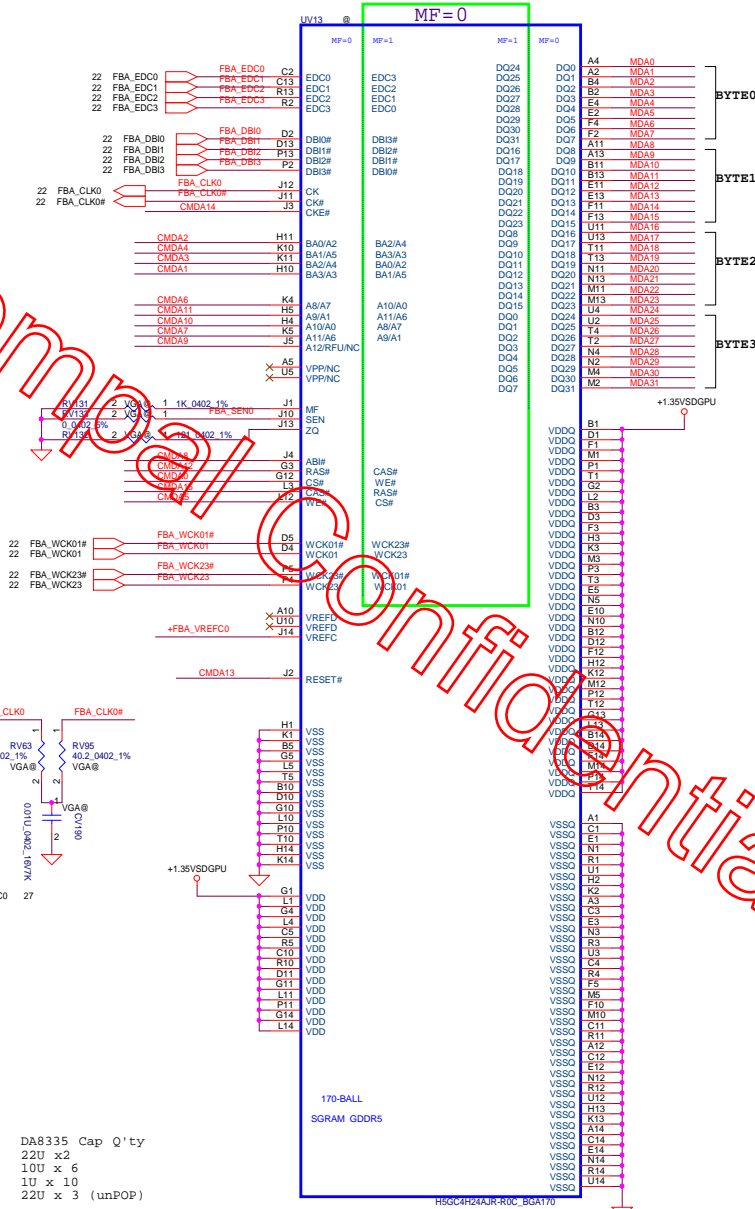


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CMD1	A3_BA3
CMD2	A2_BA0
CMD3	A4_BA2
CMD4	A5_BA1
CMD5	WE#
CMD6	A7_A8
CMD7	A6_A11
CMD8	AB1#
CMD9	A12_RFU
CMD10	A0_A10
CMD11	A1_A9
CMD12	RAS#
CMD13	RST#
CMD14	CKE#
CMD15	CAS#
CMD16	CS#
CMD17	A3_BA3
CMD18	A2_BA0
CMD19	A4_BA2
CMD20	A5_BA1
CMD21	WE#
CMD22	A7_A8
CMD23	A6_A11
CMD24	AB1#
CMD25	A12_RFU
CMD26	A0_A10
CMD27	A1_A9
CMD28	RAS#
CMD29	RST#
CMD30	CKE#
CMD31	CAS#

## Channel 0 BOT SIDE



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10U x 6  
10U x 10  
22U x 3 (unPOP)

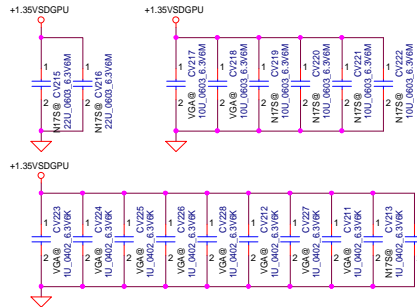
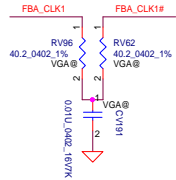
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0.1U x 6

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Issued Date	2016/11/04	Deciphered Date
2016/11/04	2018/11/04	2018/11/04
Title	N16X Lower Rank0 6/9	
Size	Document Number	Rev
C5V01 M/B LA-E892P		1.A
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## VRAM GDDR5 chips

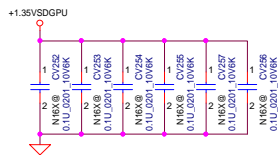
GDDR5 Mode H Mapp:

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Address	0..31	32..63
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CMD1	A3_BA3	
CMD2	A2_BA0	
CMD3	A4_BA2	
CMD4	A5_BA1	
CMD5	WE#	
CMD6	A7_A8	
CMD7	A6_A11	
CMD8	ABI#	
CMD9	A12_RFU	
CMD10	A0_A10	
CMD11	A1_A9	
CMD12	RAS#	
CMD13	RST#	
CMD14	CKE#	
CMD15	CAS#	
CMD16		CS#
CMD17		A3_BA3
CMD18		A2_BA0
CMD19		A4_BA2
CMD20		A5_BA1
CMD21		WE#
CMD22		A7_A8
CMD23		A6_A11
CMD24		ABI#
CMD25		A12_RFU
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CMD27		A1_A9
CMD28		RAS#
CMD29		RST#
CMD30		CKE#
CMD31		CAS#

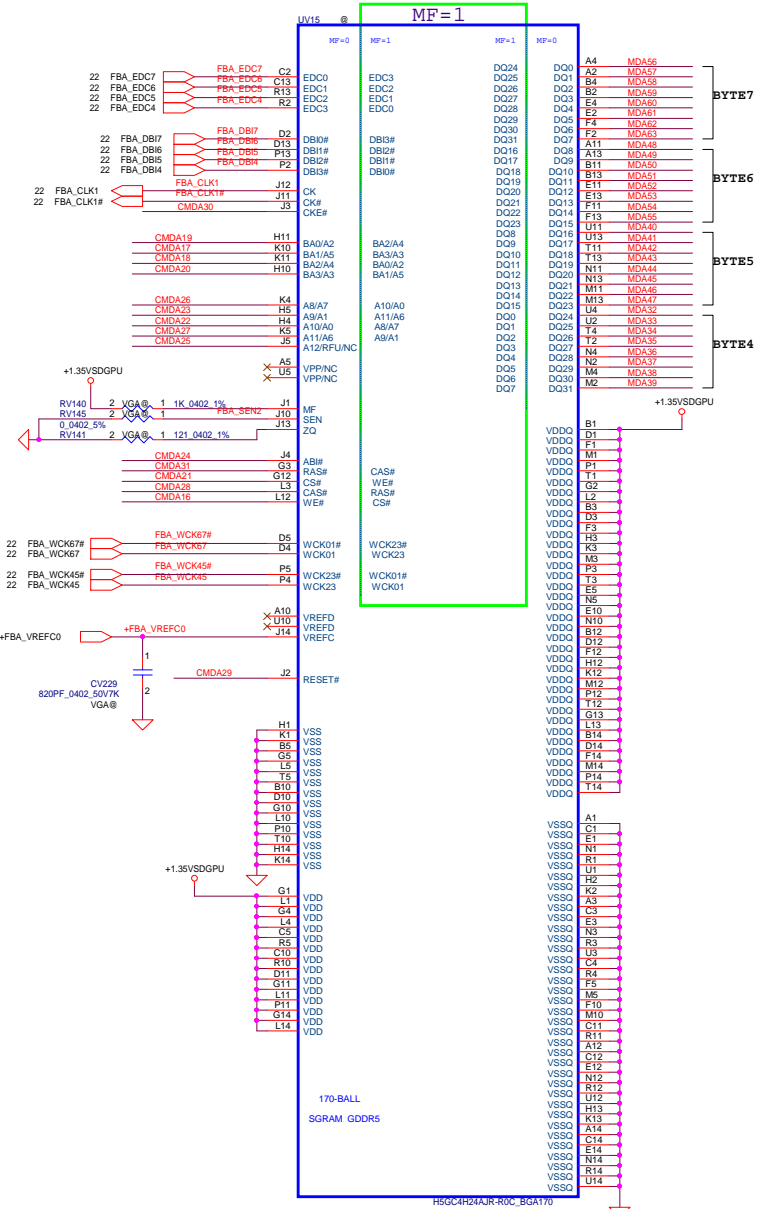


DA8335 Cap Q'ty  
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10U x 6  
1U x 10  
22U x 3 (unPOP)

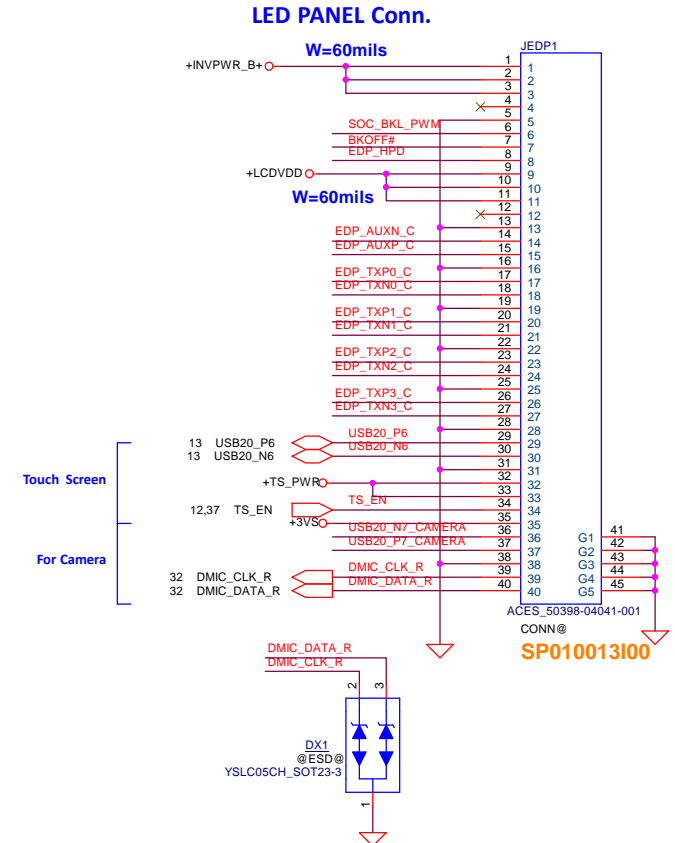
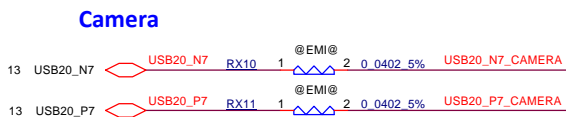
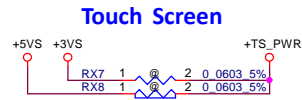
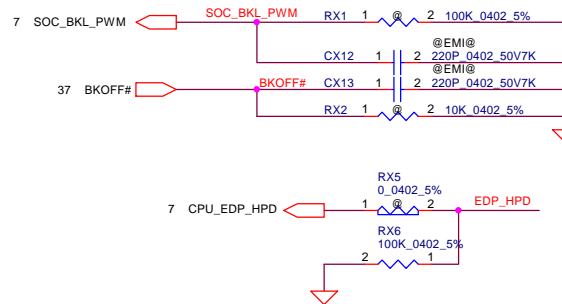
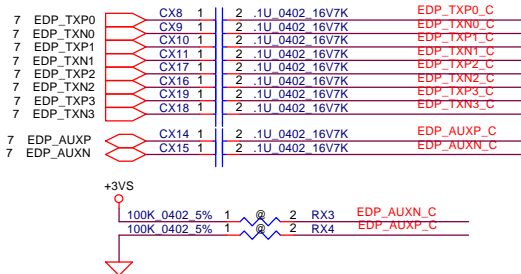
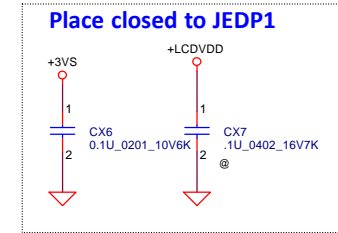
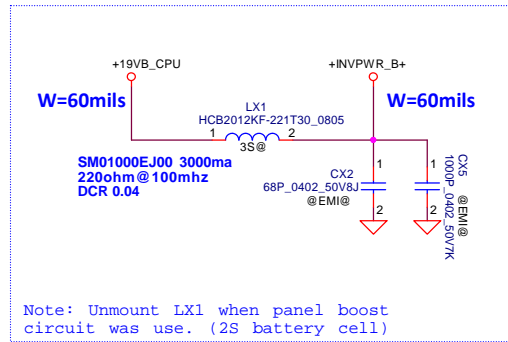
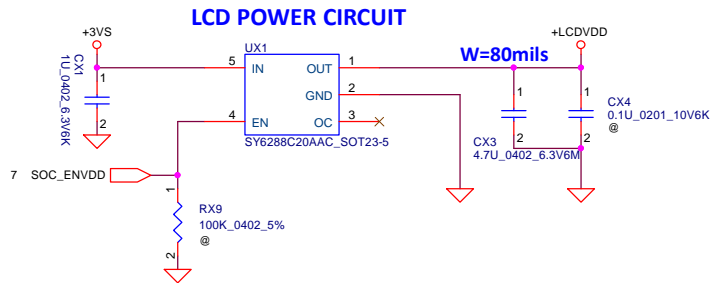
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10U x2  
1U x 8  
0.1U x 6



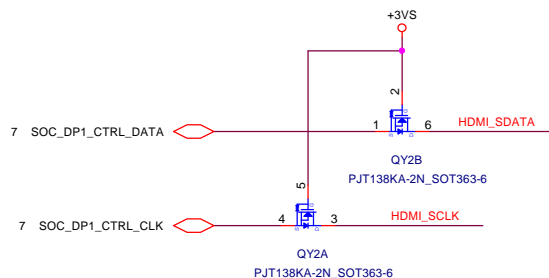
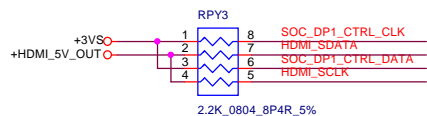
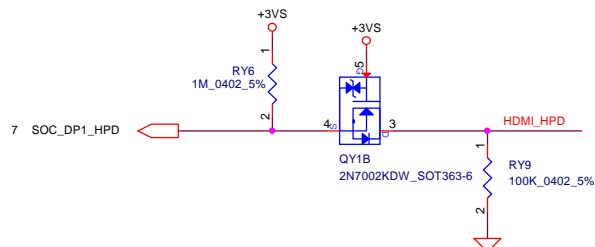
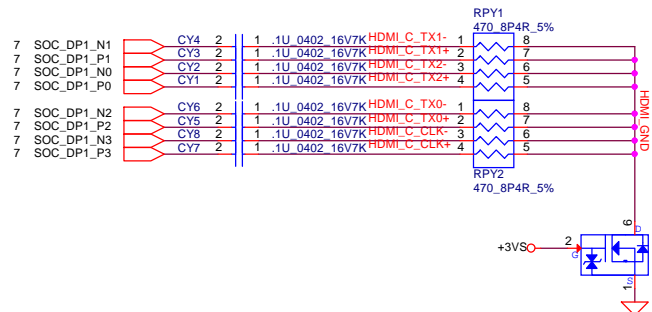
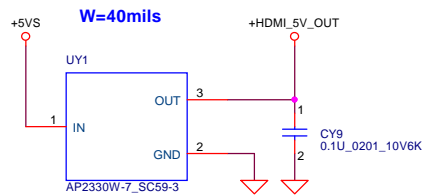
## Channel 1 BOT SIDE



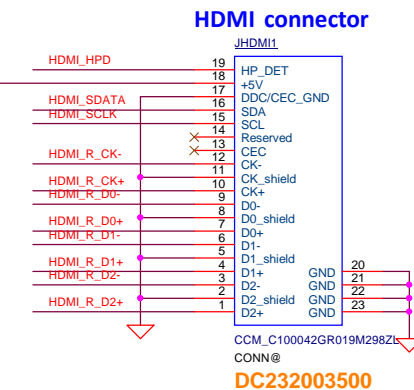
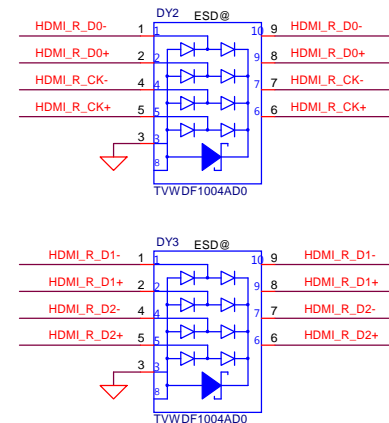
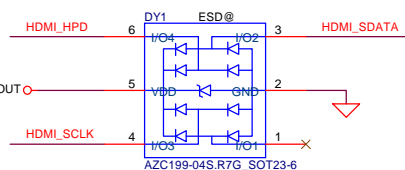
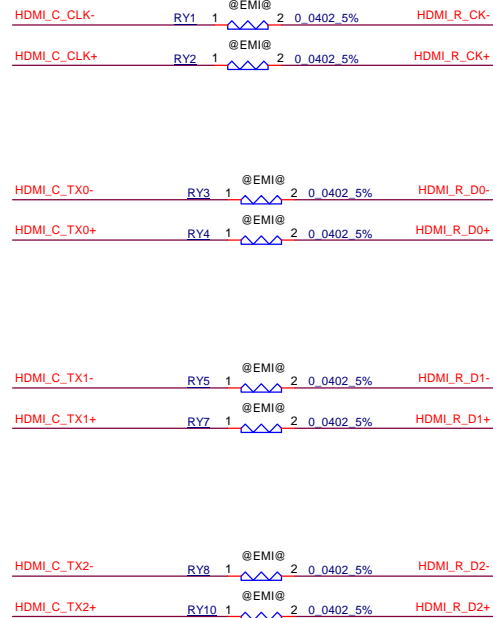
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					NI6X Lower Rank1 7/9			
					CSV01	M/B LA-E892P	1.A	



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Size	Document Number	Rev		1.A	
Custom	C5V01 M/B IA-E892P	Date:		Thursday, April 06, 2017	
Sheet		28		of 57	

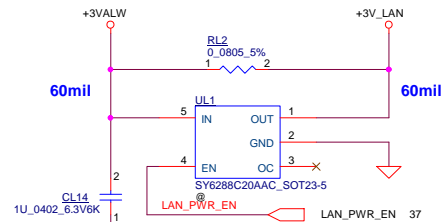


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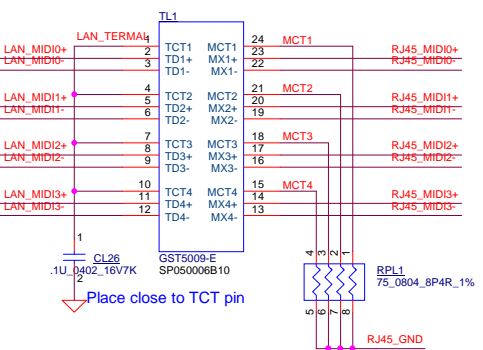
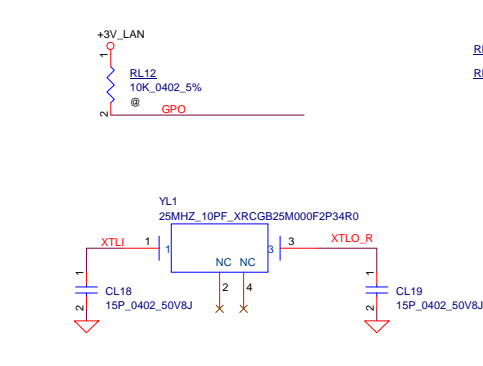


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Size	Document Number	Rev		1.A	
Custom	C5V01 M/B LA-E892P	Date: Thursday, April 06, 2017		Sheet 29 of 57	

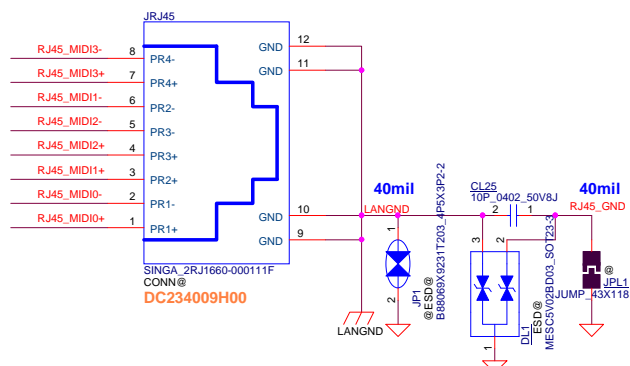
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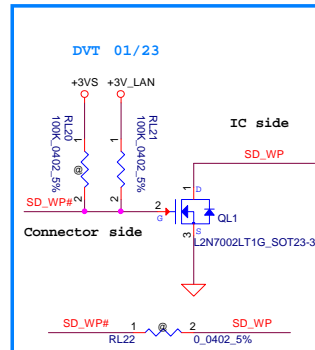
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typ:1.6V max:2.0V  
Current limit threshold 1.5-2.8A  
+3V\_LAN Rising time must >0.5ms and <100ms



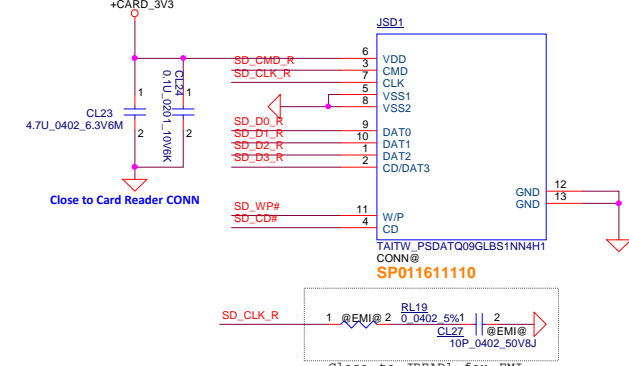
## LAN Connector



## SD Write protect inverter circuit



## Card Reader Connector



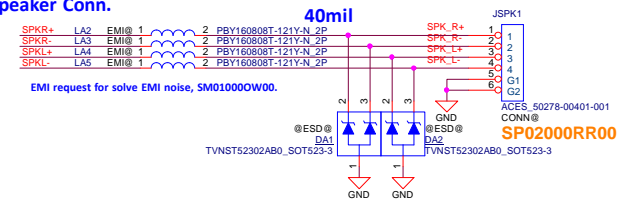
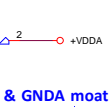
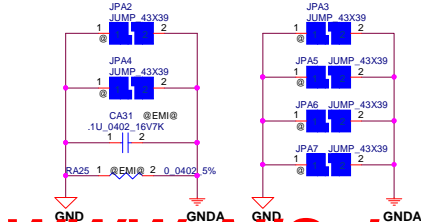
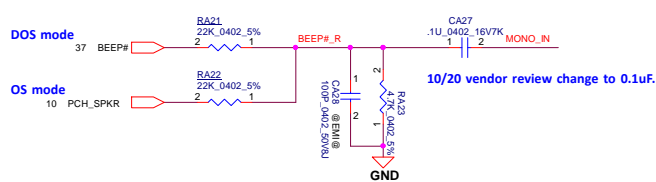
	Protect cotact		Card contact
	Write protect (Lock)	Write Enable (Unlock)	
Card Uninsert	Open	Open	Open
Card insert	Open	Close	Close

WITHOUT CARD	CARD INSERTED:LOCK	CARD INSERTED:UNLOCK
W/P GND	W/P GND	W/P GND
C/D VSS1	C/D VSS1	C/D VSS1

Security Classification			Compal Secret Data			Title		
Issued Date	2016/11/04	Deciphered Date	2018/11/04			LAN RTL8411B		
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						Customer	C5V01 M/B LA-E892P	1A
						Date:	Tuesday, April 18, 2017	Sheet 30 of 57

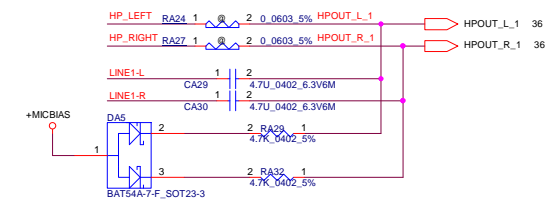


SM01000EJ00 3000mA\_220ohm@100mhz DCR 0.04

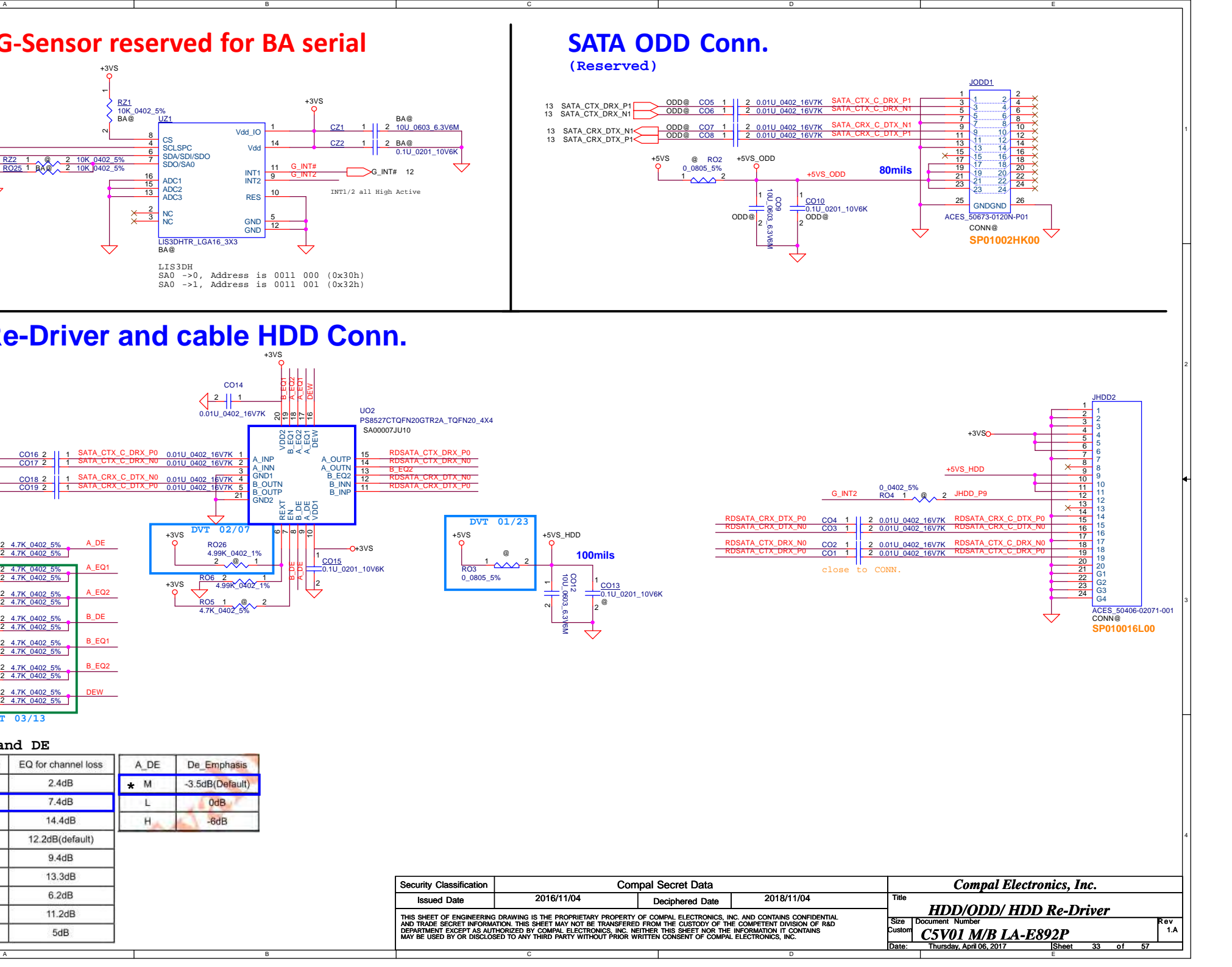
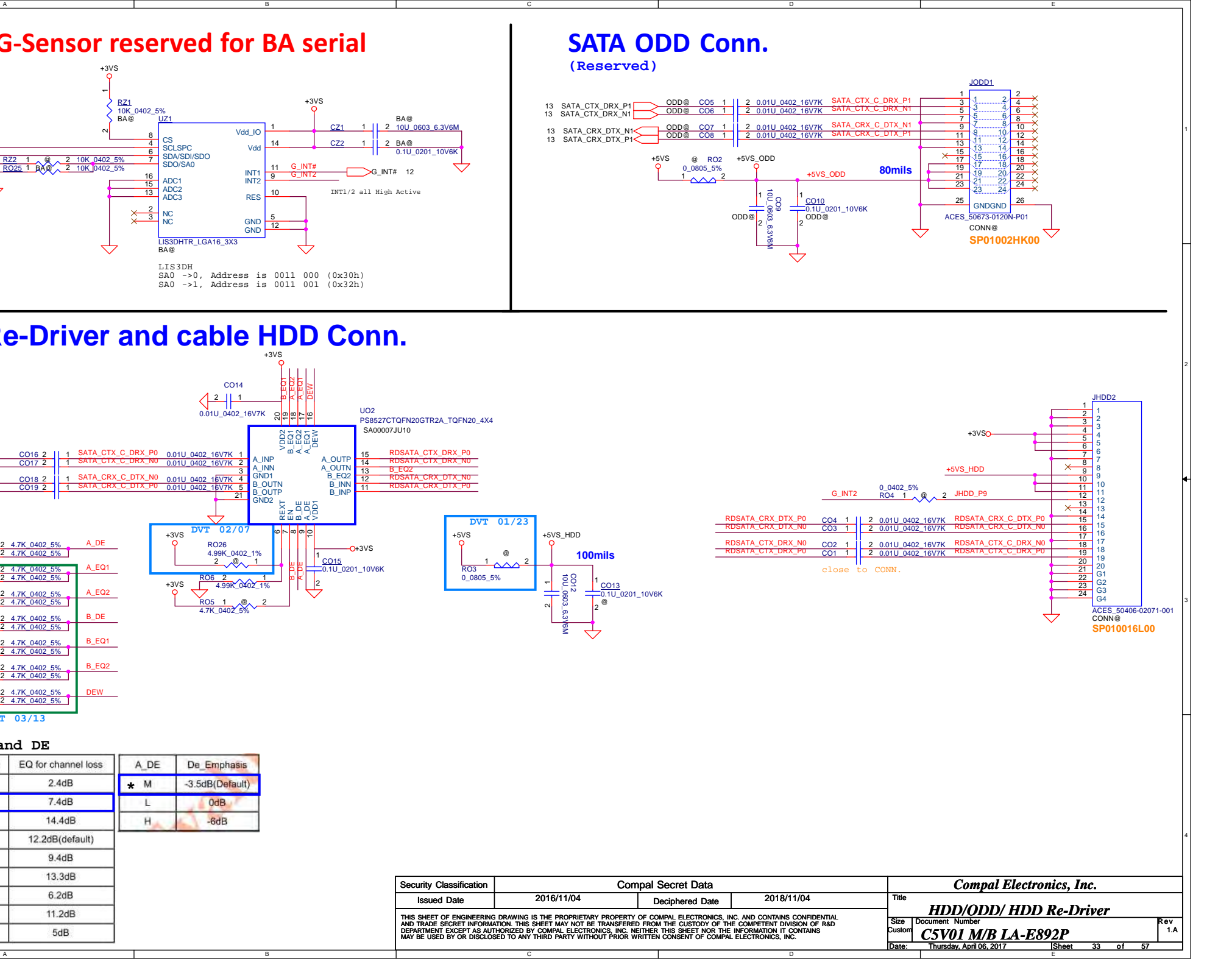
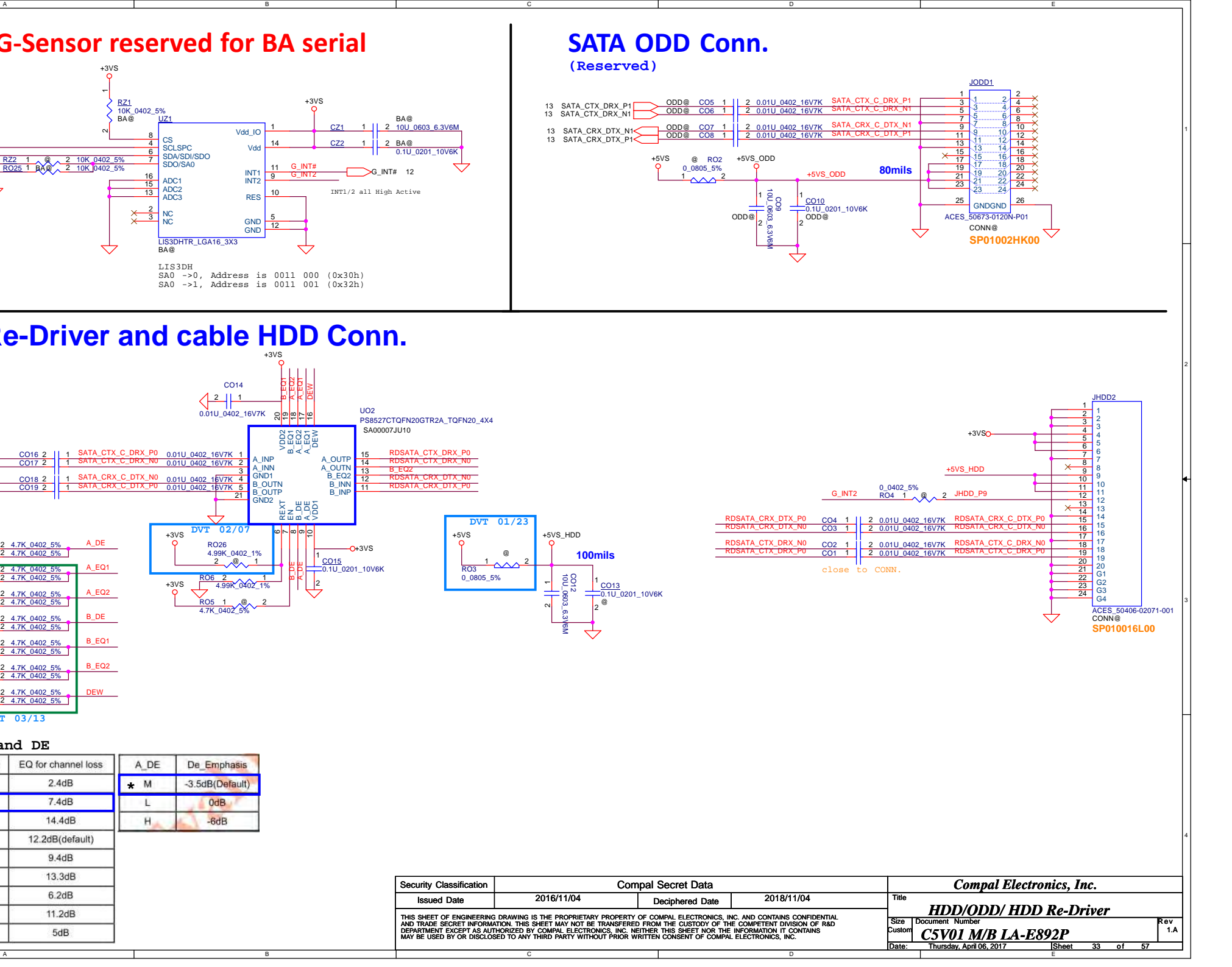


Timing diagram for eDP Conn. The diagram shows the relationship between the PCH\_DMIC\_DATA and PCH\_DMIC\_CLK signals and the DMIC\_DATA and DMIC\_CLK signals. The PCH\_DMIC\_DATA signal is shown as a red waveform, and the PCH\_DMIC\_CLK signal is shown as a blue waveform. The DMIC\_DATA and DMIC\_CLK signals are shown as red and blue waveforms, respectively. The diagram includes a 10 MHz clock source, a 0.0402 5% resistor, and a 28-pin connector. A date stamp 'DVT 01/23' is visible.

The schematic shows the +MIC2\_VREF0 pin connected to a voltage divider. The divider consists of two resistors, RA19 and RA20, both labeled as 2.2K\_0402\_5%. The top of RA19 is connected to the +MIC2\_VREF0 pin. The bottom of RA19 is connected to the top of RA20. The bottom of RA20 is connected to a common ground point labeled SLEEVE and RING2. This common ground point is also connected to pins 36 of the SLEEVE and RING2 connectors.



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					Size			Document Number	Rev
					Customer		C5V01 M/B LA-E892P	1A	
Date:		Thursday, April 06, 2017		Sheet	32	of 57			



### G-Sensor reserved for BA serial

LIS3DH  
SA0 ->0, Address is 0011 000 (0x30h)  
SA0 ->1, Address is 0011 001 (0x32h)

### SATA ODD Conn. (Reserved)

SP01002HK00

### e-Driver and cable HDD Conn.

SP010016L00

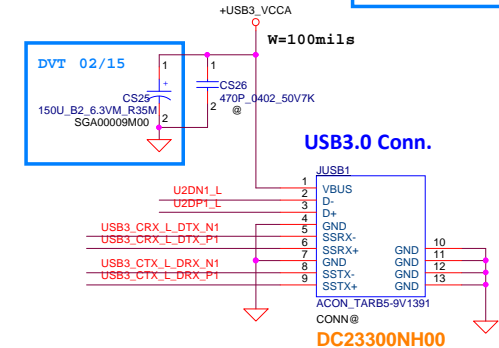
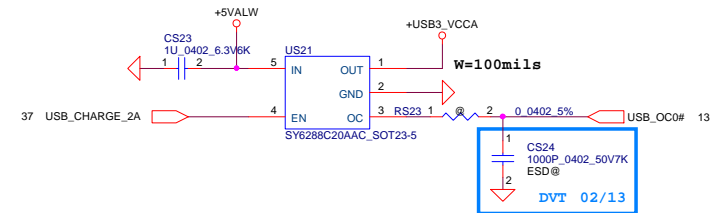
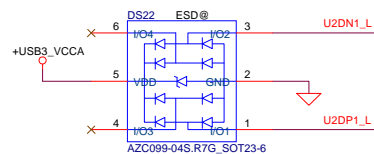
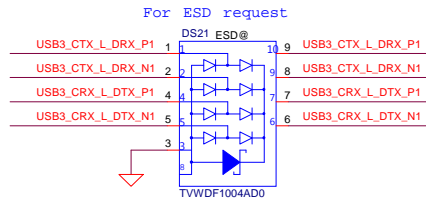
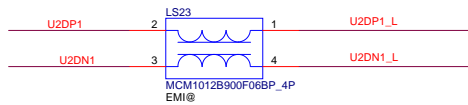
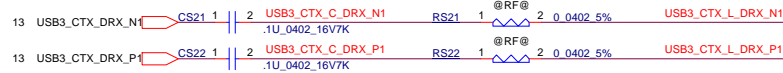
EQ for channel loss	A_DE	De_Emphasis
2.4dB	★ M	-3.5dB(Default)
7.4dB	L	0dB
14.4dB	H	-6dB
12.2dB(default)		
9.4dB		
13.3dB		
6.2dB		
11.2dB		
5dB		

Security Classification				Compal Secret Data				Compal Electronics, Inc.			
Issued Date		2016/11/04		Deciphered Date		2018/11/04		Title			
								HDD/ODD/ HDD Re-Driver			
Size		Document Number		Date		Thursday, April 06, 2017		Sheet		33 of 57	
Custom		C5V01 M/B LA-E892P		Rev		1.A					



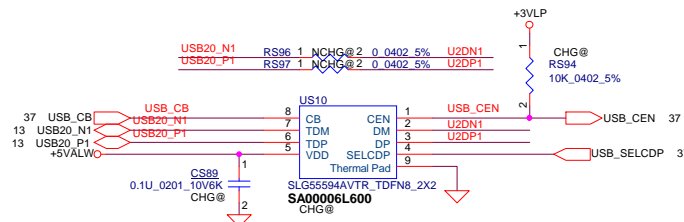


## USB3.0 (Port 1)

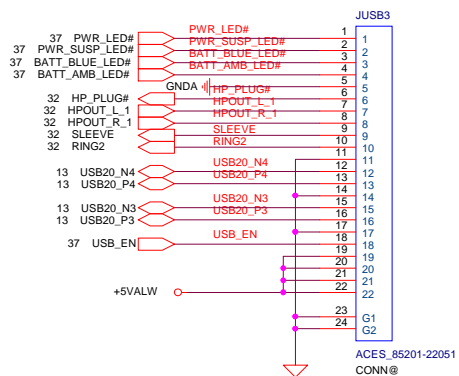


## USB Host Charger

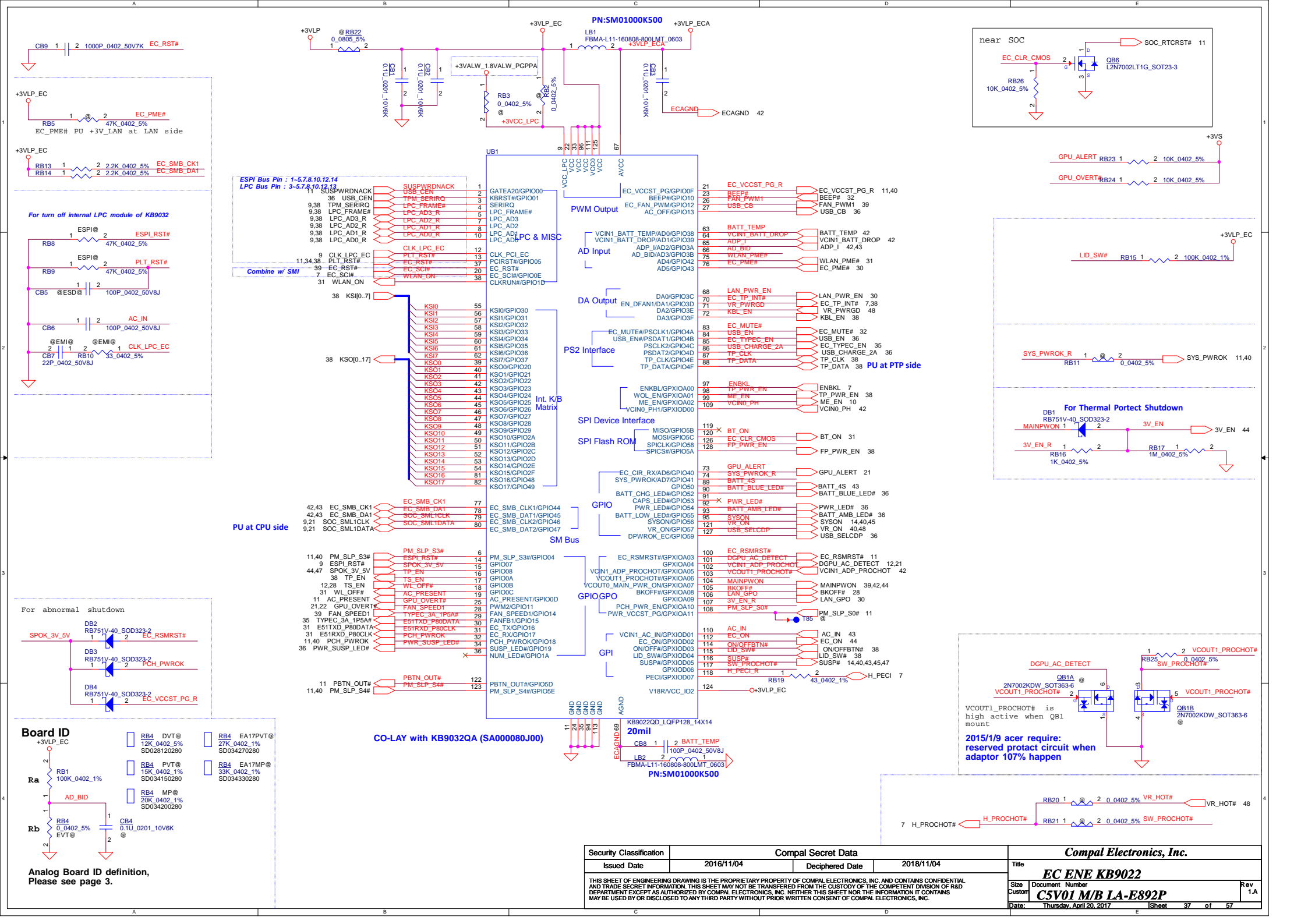
CB	SELCDP	
0	X	DCP(Dedicated Charging Port) autodetect with mouse/keyboard wakeup
1	0	S0 charging with SDP(Standard Downstream Port) only
1	1	S0 charging with CDP(Charging Downstream Port) or SDP only



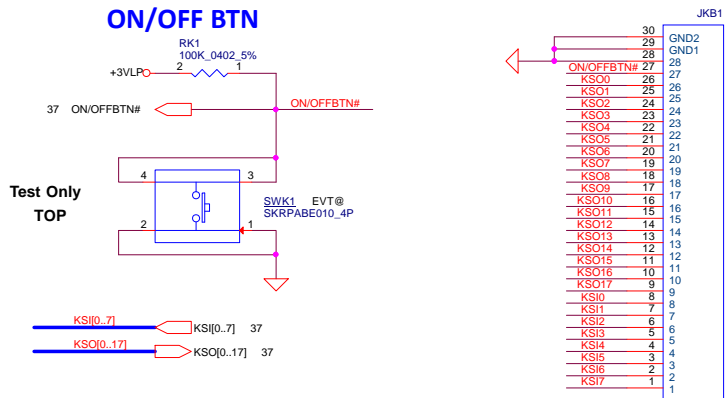
## USB/B (USBx2, AUDIO, LEDx2)



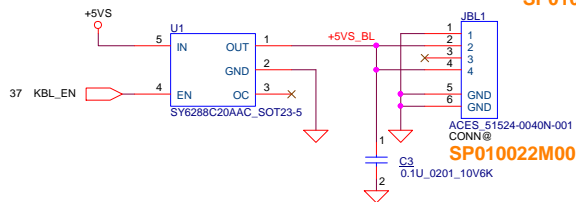
Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2016/11/04	Deciphered Date	2018/11/04	Title	USB Conn/USB B
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				Date: Thursday, April 06, 2017	Rev 1.A
				Sheet 36 of 57	



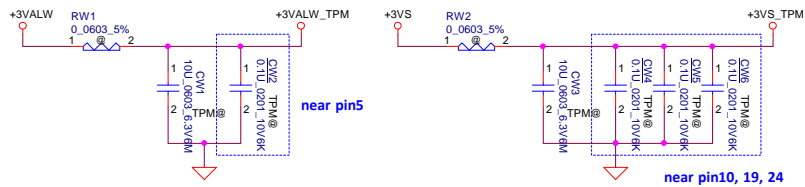
## KB Conn.



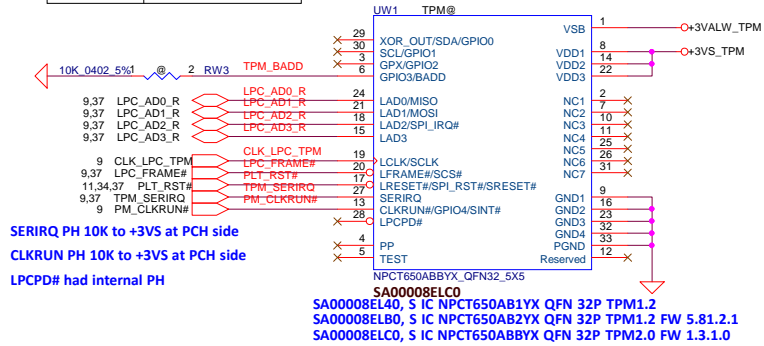
## KB BackLight



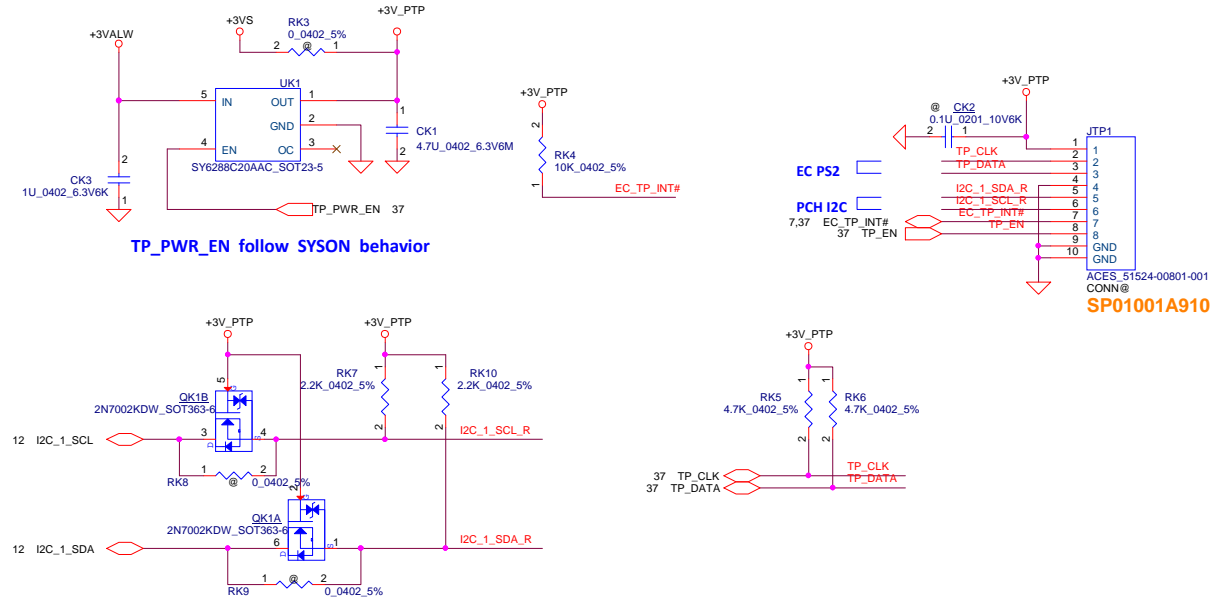
## TPM



BADD	SELECTION
* 1	Aeh(write), Afh(read)



## TP/B Conn.

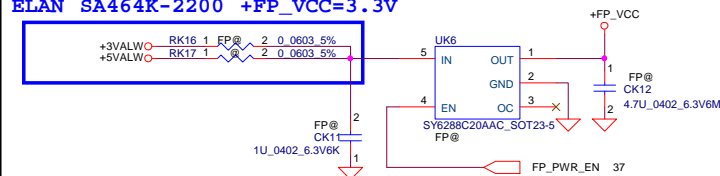


## Finger Print

Power Souce Check

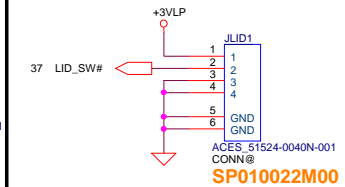
EGIS ETU801 +FP\_VCC=5V

ELAN SA464K-2200 +FP\_VCC=3.3V



## Lid Switch

(Hall Effect Switch)

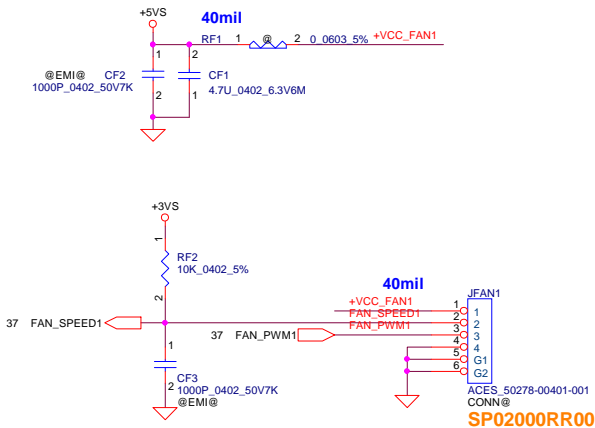


PIN	ETU801	SA464K-2200
1	+FP_VCC (5V)	+FP_VCC (3V)
2	USBP	D+
3	USBN	D-
4	GND	GND
5	NC	NC
6	NC	NC
7	NC	NC
8	NC	NC

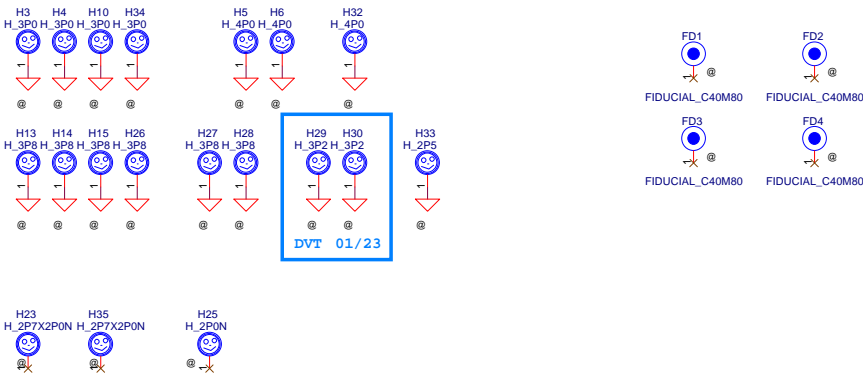
Security Classification				Compal Secret Data				Compal Electronics, Inc.			
Issued Date		2016/11/04		Deciphered Date		2018/11/04		Title			
Size		Document		Number		C5V01 M/B LA-E892P		Rev			
Date:		Thursday, April 06, 2017		Sheet		38		of 57			

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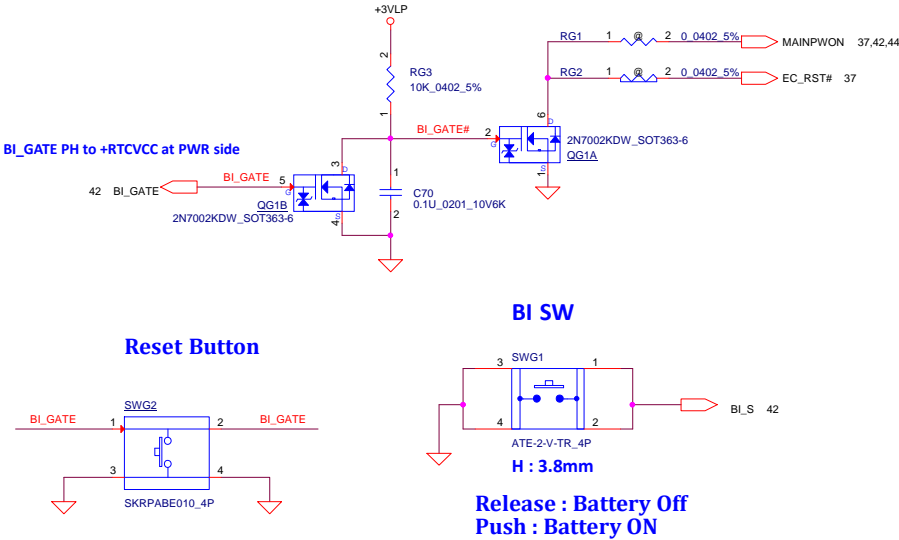
FAN1 Conn



Screw Hole

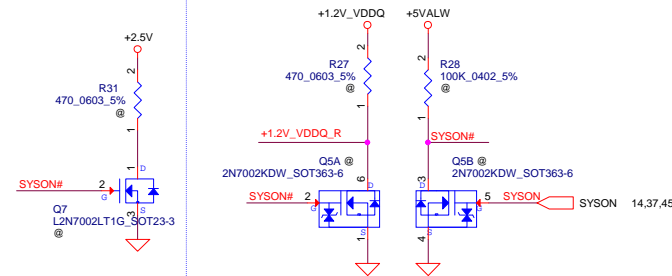
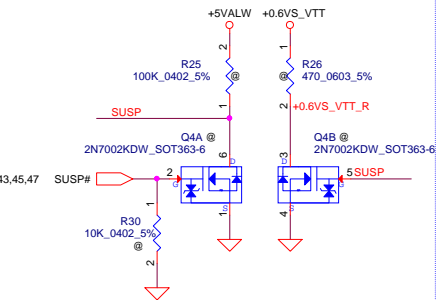
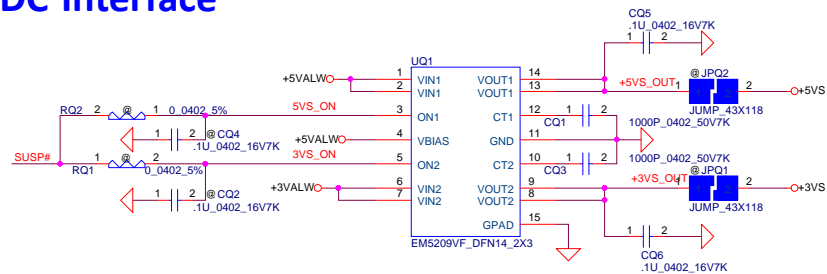


Reset Circuit

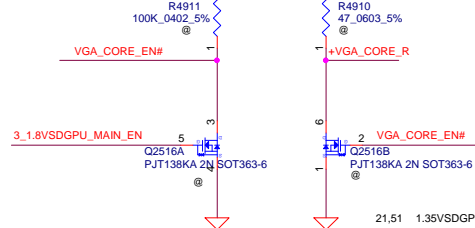
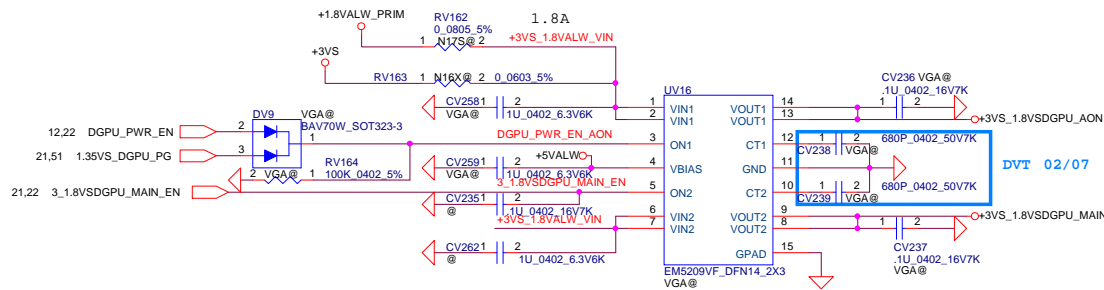
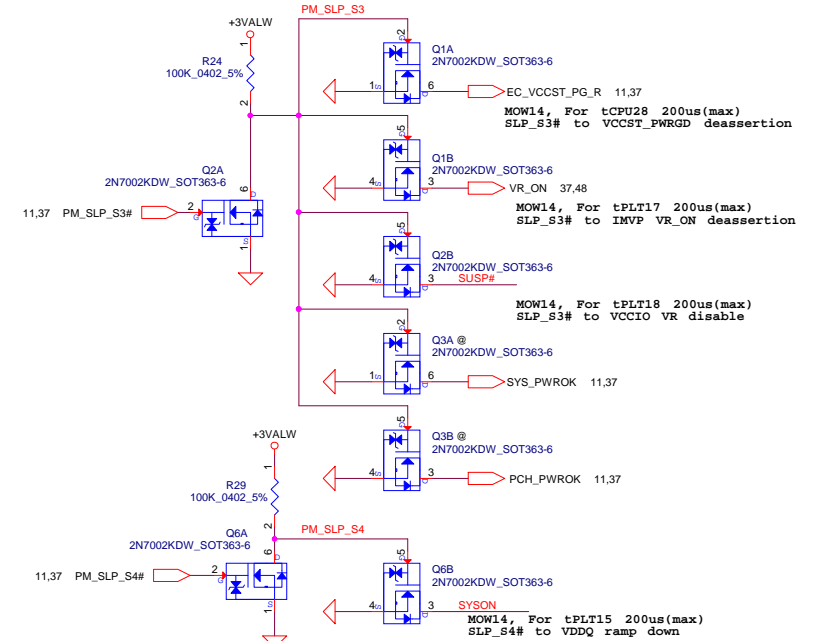


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Issued Date	2016/11/04	Deciphered Date	2018/11/04	Title	FAN & Screw Hole & Reset	
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				Custom	C5V01 M/B LA-E892P	1.A
				Date:	Thursday, April 06, 2017	Sheet 39 of 57

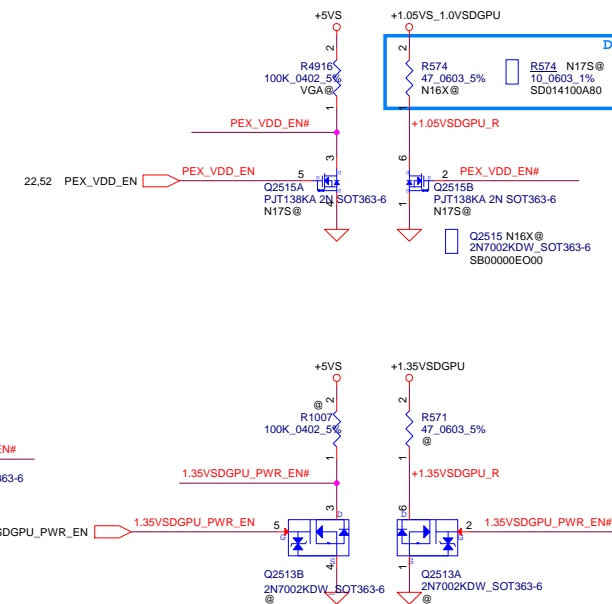
## DC Interface



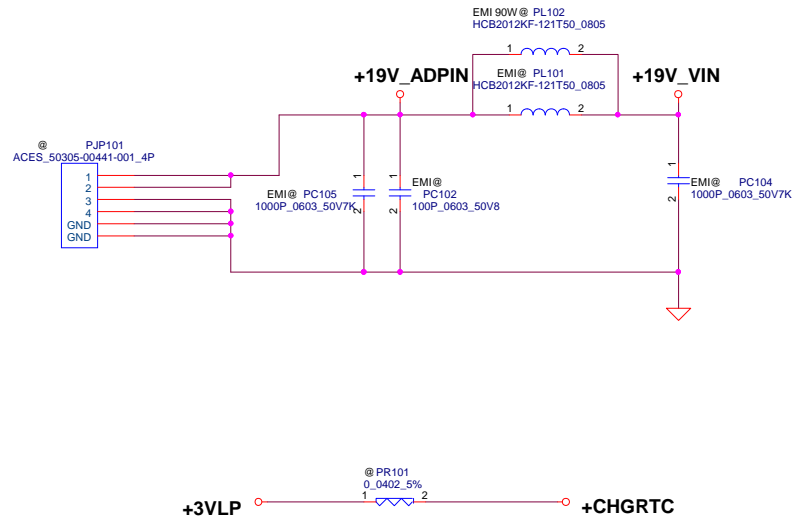
## For Power ON/Off Sequence



+3VS to +3VSDGPU\_AON for GPU



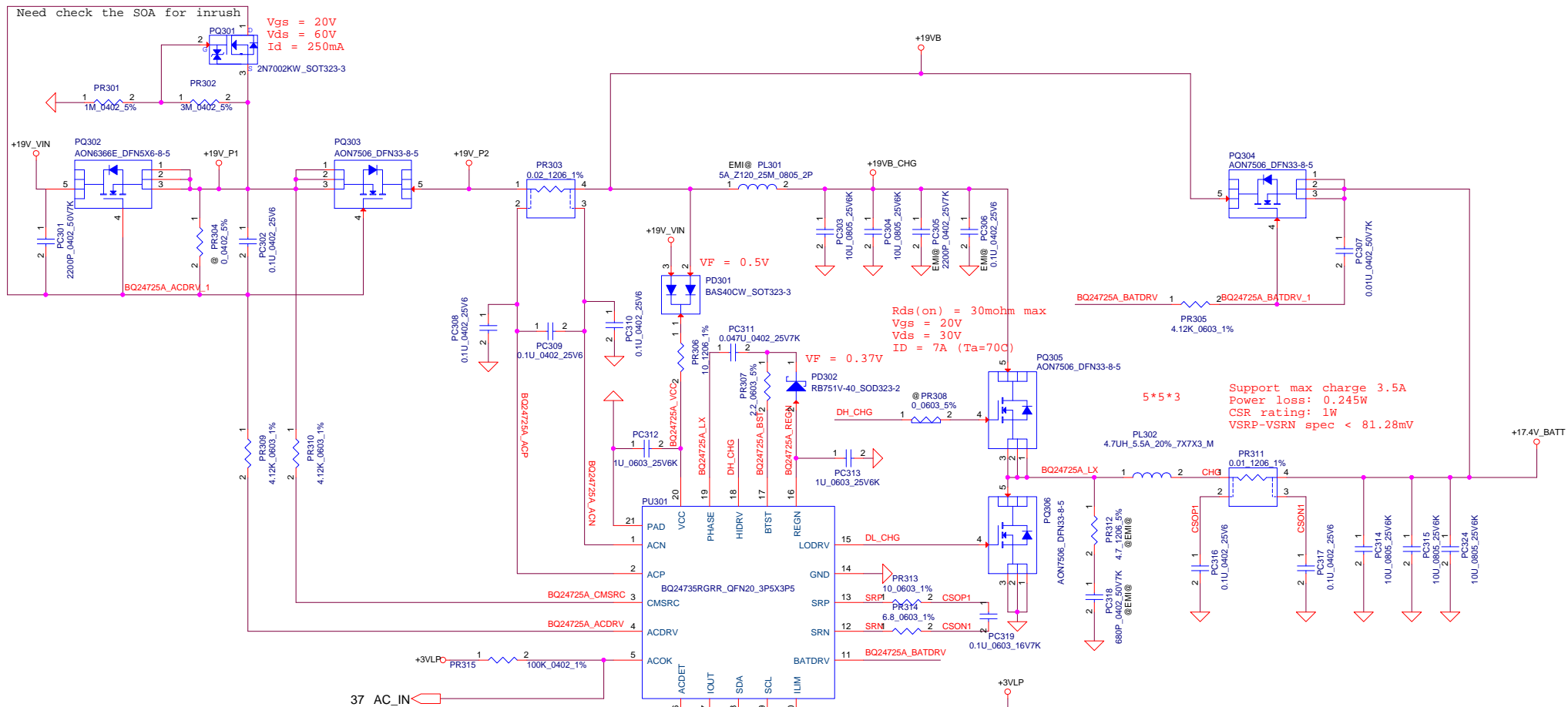
Security Classification		Compal Secret Data		Compal Electronics, Inc.					
Issued Date	2016/11/04	Deciphered Date	2018/11/04	Title					
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				Size	Document Number			Rev 1.A	
				Custom	C5V01 M/B LA-E892P				
				Date: Thursday, April 06, 2017				Sheet 40 of 57	



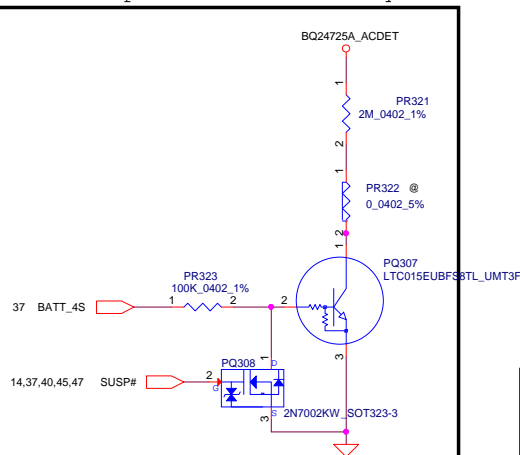
Security Classification		Compal Secret Data		Compal Electronics, Inc.		
Issued Date		2016/11/04	Deciphered Date		2018/11/04	Title
PWR DCIN / Pre-charge						
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		C5V01		M/B LA-E892P	0.1	
		Date:		Thursday, April 06, 2017	Sheet	41 of 57



# Protection for reverse input



## For 4S per cell 4.35V battery



### Vin Detector

	Min.	Typ	Max.
L-->H	17.16V	17.63V	18.12V
H-->L	16.76V	17.22V	17.70V

$$VILIM = 20 * ILIM * Rsr$$

$$ILIM = 3.3 * 100 / (100 + 316) / 20 / 0.01$$

$$= 3.966 A$$

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Issued Date	2016/11/04	Deciphered Date	2018/11/04	Title	CHARGER
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Size	Document Number	Common Circuit			Rev 0.1
Date:	Thursday, April 06, 2017	Sheet	43 of 57		

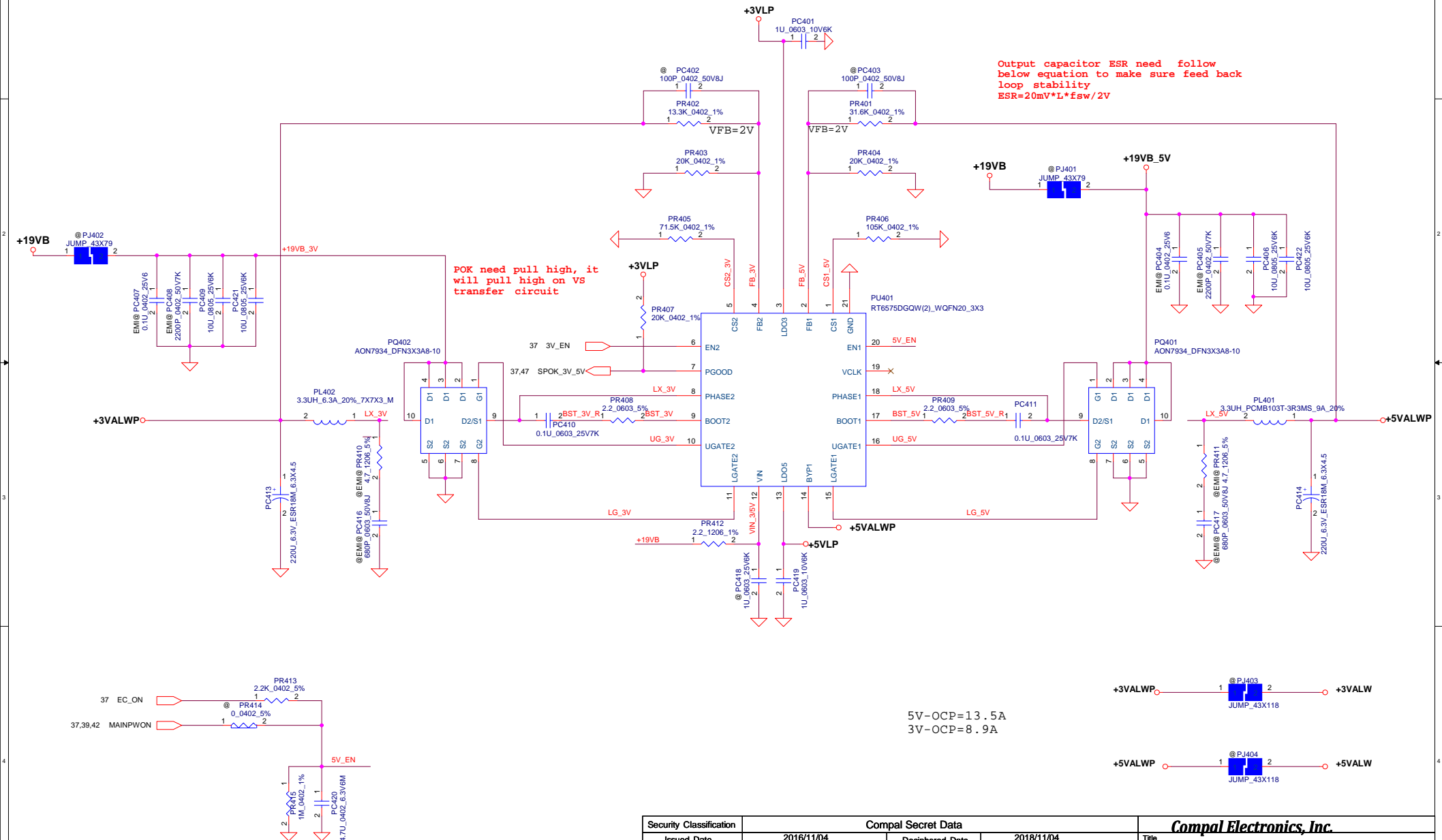
## Module model information

RT6575D\_DMOS\_single\_V1.mdd  
RT6575D\_DMOS\_dual\_V1.mdd

H/S  $R_{ds(on)}$ :typ:12.4mOhm, max:15.8mOhm  
 $I_{dsm}(TA=25)=13A$ ,  $I_{dsm}(TA=70)=7.8A$   
 $P_{loss}=0.42W$

L/S  $R_{ds(on)}$ :typ:9.1mOhm, max:11.6mOhm  
 $I_{dsm}(TA=25)=15A$ ,  $I_{dsm}(TA=70)=9A$   
 $P_{loss}=0.14W$

CHOKE:4.7uH, DCR 35mOhm  
 $P_{loss}=1.77W$



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Issued Date	2016/11/04	Deciphered Date	2018/11/04	Size	Document Number
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				Sheet	44 of 57

Compal Electronics, Inc.

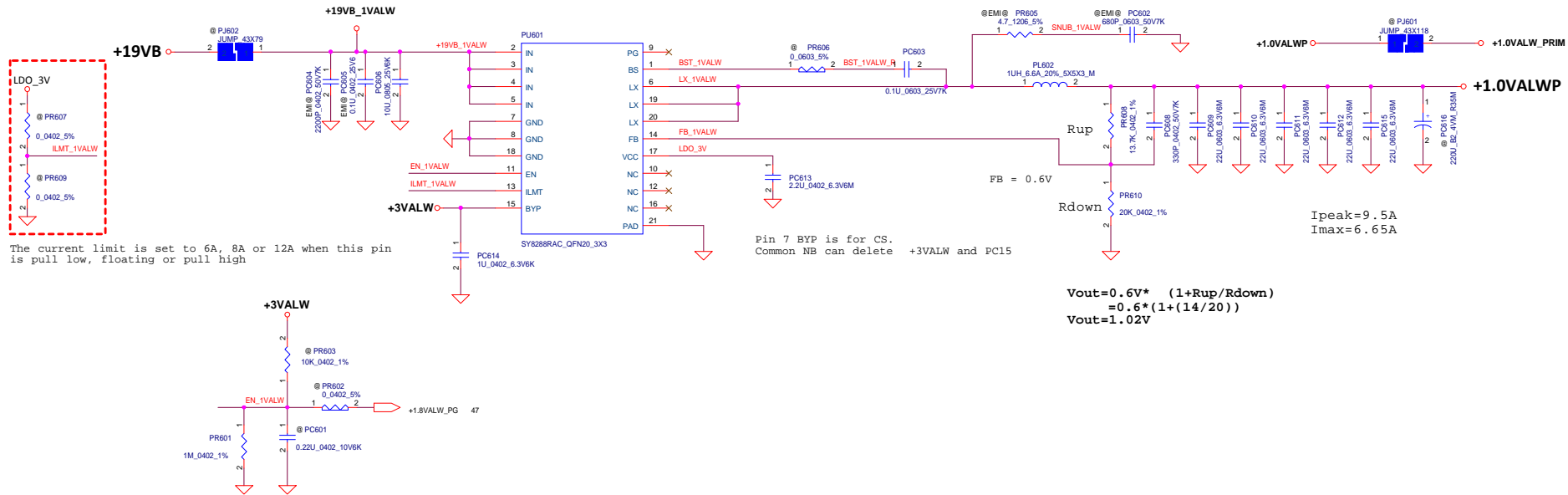
PWR-3.3VALWP/5VALWP

C5V01 M/B LA-E892P

Rev 0.1

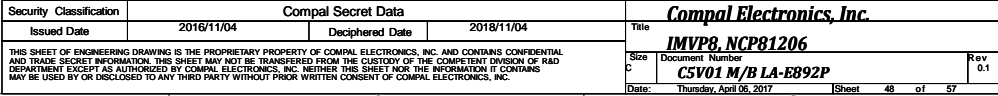


EN pin don't floating  
If have pull down resistor at HW side, pls delete PR702

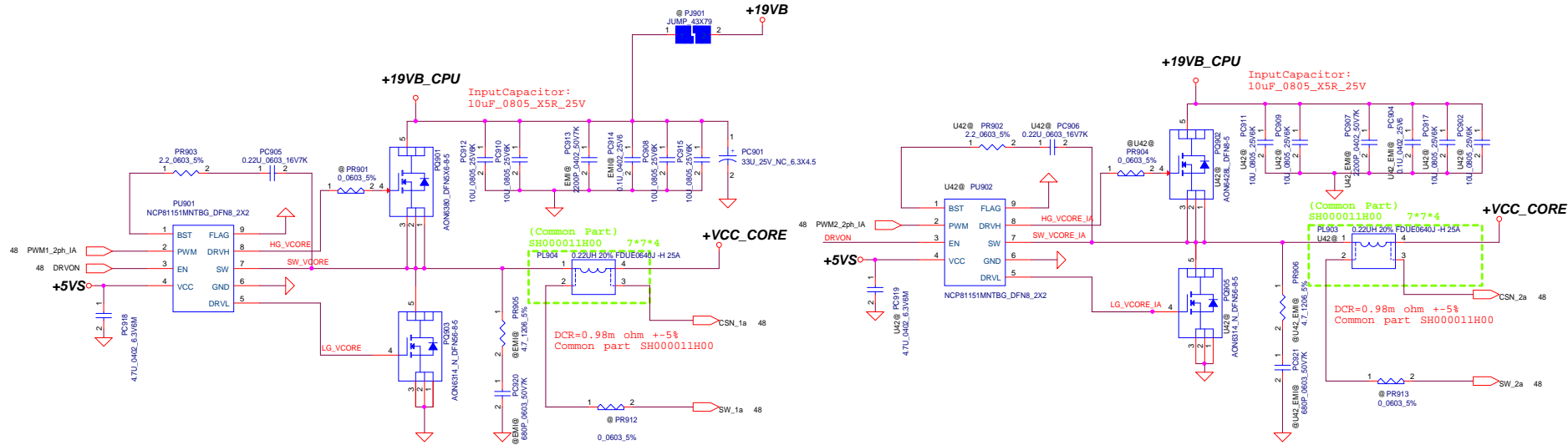


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Issued Date	2016/11/04	Deciphered Date	2018/11/04	Title	VCCP
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				C	C5V01 M/B LA-E892P
				Date:	Thursday, April 06, 2017
				Sheet	46 of 57
				Rev	0.1

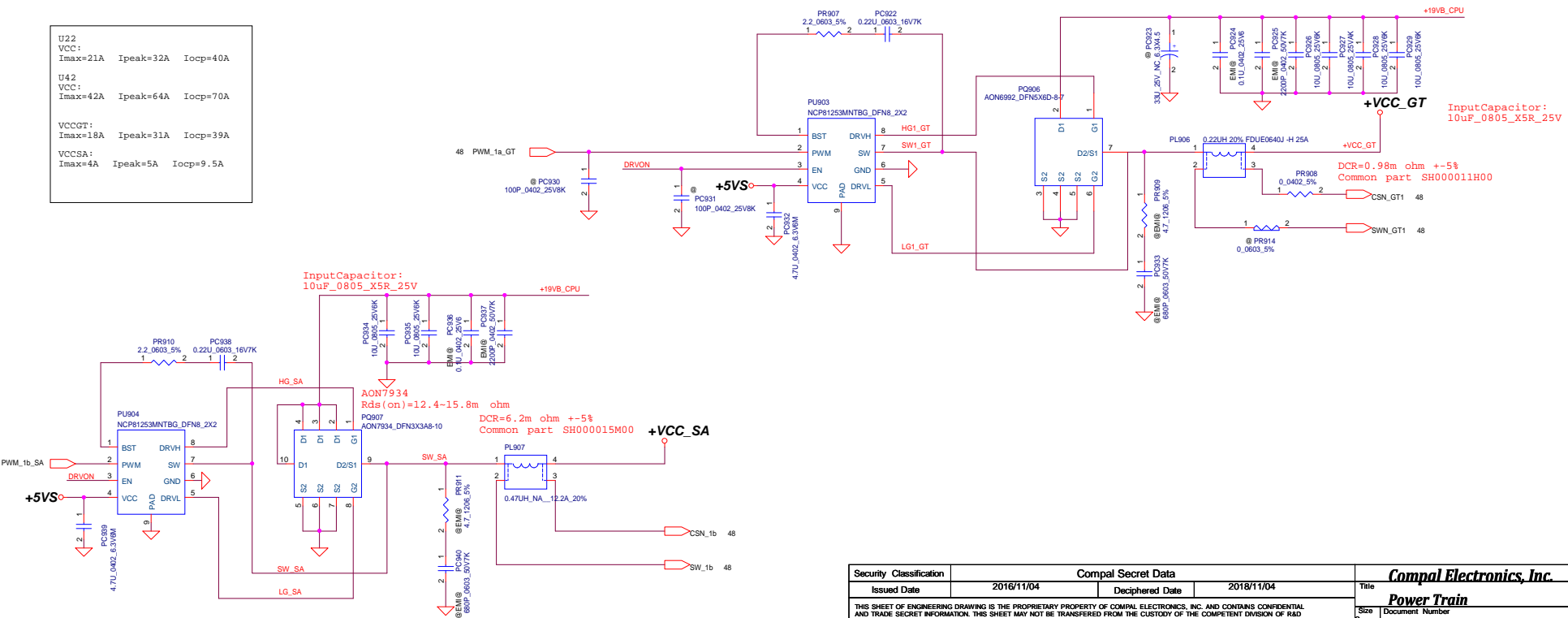




change PL9002, PL9003  
SM01000C000 to comm  
part SM01000P200



U22	VCC:	I <sub>max</sub> =21A	I <sub>peak</sub> =32A	I <sub>ocp</sub> =40A
U42	VCC:	I <sub>max</sub> =42A	I <sub>peak</sub> =64A	I <sub>ocp</sub> =70A
VCCGT:	I <sub>max</sub> =18A	I <sub>peak</sub> =31A	I <sub>ocp</sub> =39A	
VCCSA:	I <sub>max</sub> =4A	I <sub>peak</sub> =5A	I <sub>ocp</sub> =9.5A	



Security Classification	Compal Secret Data		Title	
Issued Date	2016/11/04	Deciphered Date	2018/11/04	Document Number
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Date: Thursday, April 06, 2017				Sheet 49 of 57

Compal Electronics, Inc.

Power Train

C5V01 M/B LA-E892P

2016/10/26  
VCORE Output Capacitor:  
U42  
22uF\_0603\*39  
1uF\_0201\*35  
220uF \*3  
UNPOP  
22\_0603\*9

2016/10/26  
VCORE Output Capacitor:  
U22  
22uF\_0603\*33  
1uF\_0201\*35  
UNPOP  
22\_0603\*9

220uF\*1  
22uF\*36  
1uF\*9  
0.47uF\*4  
unpop:  
22uF \*8  
1uF\*1

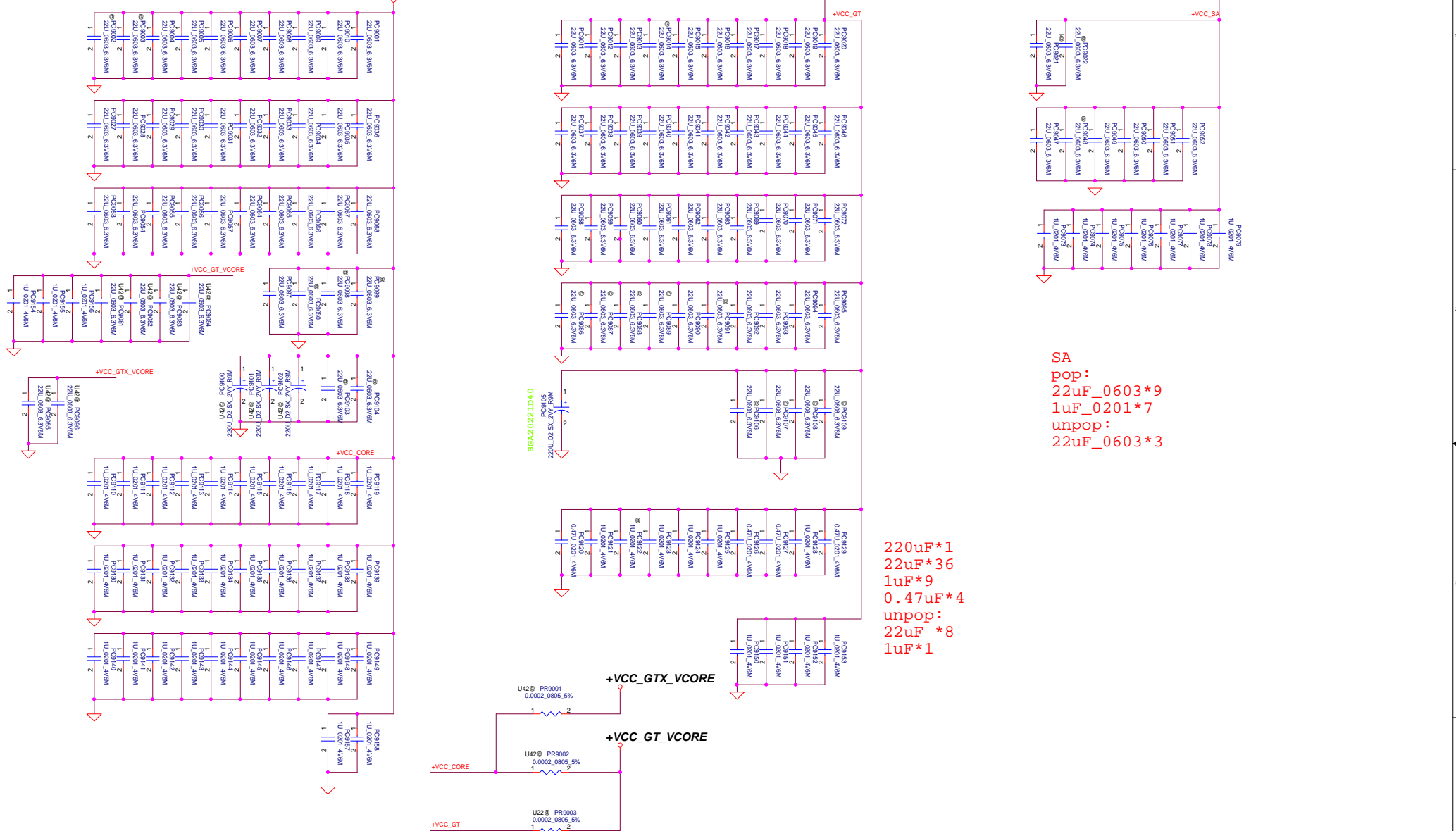
SA  
pop:  
22uF\_0603\*9  
1uF\_0201\*7  
unpop:  
22uF\_0603\*3

WWW.AliSaler.Com

+VCC\_CORE

+VCC\_GT

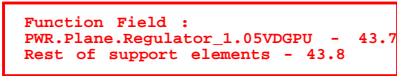
+VCC\_SA



Security Classification		Compal Secret Data		Title	
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2016/11/04		2018/1/04		2018/1/04	
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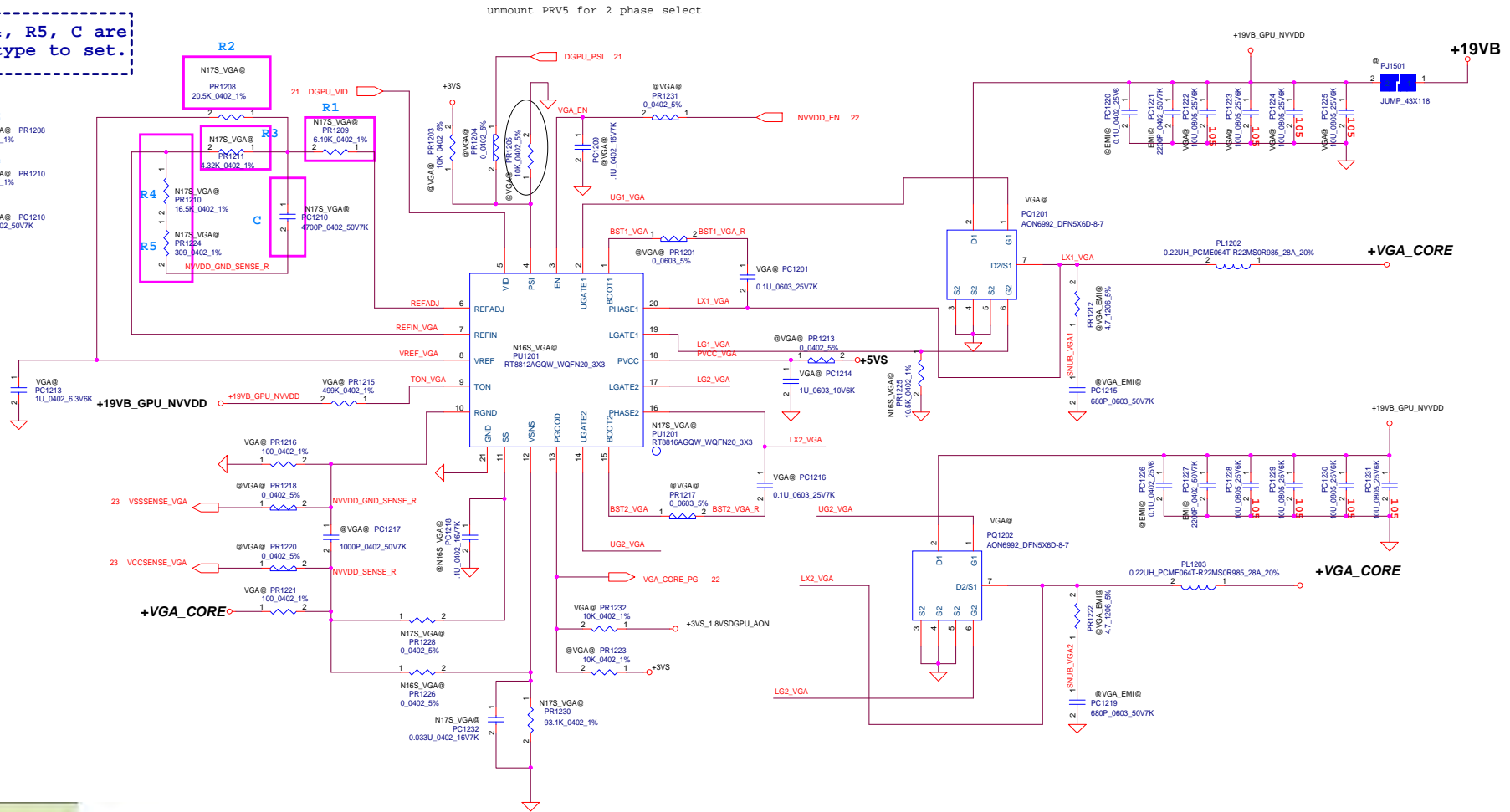


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Module model information
SY8032_v2.mdd
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$$\begin{aligned} V_{out} &= 0.6V * (1 + R_{up}/R_{down}) \\ &= 0.6V * (1 + (7.68/10)) = 1.061 \quad (1.01\%) \\ &= 0.6V * (1 + (7.87/10)) = 1.072 \quad (2.1\%) \\ V_{out} &= 0.6V * (1 + (6.81/10)) = 1.0086V \end{aligned}$$

R1, R2, R3, R4, R5, C are based on VGA type to set.

R1 N16S\_VGA@ PR1209 20K\_0402\_1%  
R2 N16S\_VGA@ PR1208 20K\_0402\_1%  
R3 N16S\_VGA@ PR1211 2K\_0402\_1%  
R4 N16S\_VGA@ PR1210 10K\_0402\_1%  
R5 N16S\_VGA@ PR1224 0.0402\_5%  
C N16S\_VGA@ PC1210 2700P\_0402\_50V7K



#### PWM-VID Specification

Config B	
Vmin	V 0.6
Vmax	V 1.2
Vboot	V 0.9
Voltage Step Vstep	mV 6.25
Number of Voltage Levels N	level 96
PWM Frequency F <sub>PWM</sub>	MHz 1.125
PWM Minimum Pulse Width T <sub>DMIN</sub>	ns 9.26
VID Transient Time T	us <100
Component Value	
R1 (1%)	KΩ 20
R2 (1%)	KΩ 20
R3 (1%)	KΩ 2
R4 (1%)	KΩ 18
R5 (1%)	KΩ 0
C	nF 2.7

N17x DG-07875-001\_v08.pdf:

Table 7.8 PWM-VID Spec and Component Values

PWM-VID Specification		
	Unit	Config
Vmin	V	0.3
Vmax	V	1.3
Vboot	V	0.8
Voltage Step Vstep	mV	6.25

Table 7.8 PWM-VID Spec and Component Values

PWM-VID Specification		
	Unit	Config
Number of Voltage Levels N	level	160
PWM Frequency F <sub>PWM</sub>	kHz	675
PWM Minimum Pulse Width T <sub>DMIN</sub>	ns	9.26
VID Transient Time T	us	<100
Component Value		
R1 (1%)	KΩ	6.19
R2 (1%)	KΩ	20.5
R3 (1%)	KΩ	4.32
R4 (1%)	KΩ	16.5
R5 (1%)	KΩ	0.309
C	nF	4.7

Table 6. EDP-Continuous<sup>3</sup>

Products	VRAM Type	GPU Core
N16S-GMR	GDDR5	19.0
	DDR3/L	21.0
N16S-GTR	GDDR5 @ 2.0 GHz	26.5
	GDDR5 @ 2.5 GHz	26.5
	DDR3/L	26.0
N16S-GXR	GDDR5	35.4

Table 7. EDP-Peak<sup>3</sup>

Products	VRAM Type	GPU Core
N16S-GMR	GDDR5	34.0
	DDR3/L	39.5
N16S-GTR	GDDR5 @ 2.0 GHz	53.0
	GDDR5 @ 2.5 GHz	53.0
	DDR3/L	51.0
N16S-GXR	GDDR5	54.0

Table 7. Output EDP-Continuous

	NVDD	GPU FBIO	FB Total <sup>3</sup>	1.0V Total <sup>1</sup>	1.8V Total <sup>2</sup>
Product	(A)	(A)	(A)	(A)	(A)
N17S-G1	29.7	2.0	3.4	0.1	0.3
N17S-LG	15.4	1.6	2.8	0.1	0.2

Table 8. Output EDP-Peak

	NVDD	GPU FBIO	FB TOTAL <sup>4</sup>	1.0V Total <sup>1</sup>
Product	(A)	(A)	(A)	(A)
N17S-G1	59.2	3.2	6.6	0.2
N17S-LG	49.6	3.2	6.6	0.2



## Version change list (P.I.R. List)

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for PWR

Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	Date	Phase
01	prevent part damage				PC410 and PC411 change to 0603 size	1/23	DVT
02	reduce part count				PR515,PR804,PR806,PR812,PR813,PR865,PR847,PR860,PR876,PR863,PR852,PR864,PR875,PR901,PR912,PR904,PR913,PR914 change to R-short	1/23	DVT
03	voltage level too high	3.37V change to 3.33V			PR402 change to 13.3K from 13.7K	1/23	DVT
04	SPOK voltage level				PR407 change to 20K from 100K	1/23	DVT
05	SMT	close SMT stencil problem			PJ9001, PJ9002, PJ9003 change to 0.2m ohm	1/23	DVT
06	DC S5 power consumption	meet DC S5 2.5mA spec			PR209 change to 750K from 10K PR211 change to 150K from 2K	1/23	DVT
07	prevent shortage				PL907 change to common part SH00001ED00 PQ502 change to AON7506	1/23	DVT
08	For N17s colay N16S				add PR1015 Oohm and PC1018 for transient PR1009 change to Oohm from R-Short PR1013 change to Oohm from 100 ohm	1/23	DVT
09	For power sequence				PC1218 change to unpop for rise time PR1231 change to 1K from 20K for sequence PR1003 change to 100K from 1M PR1002 change to Oohm from 40.2K	1/23	DVT
10	For EMI request				PJ301 change to PL301	1/23	DVT
11	CPU transient	meet CPU spec			PR805 change to 1.69K from 1.78K PR814 change to 806ohm from 1K PR874 change to 97.6k from 93.1K PC821 change to 0.22u from 0.1uF PC820 change to 8200P from 0.01uF PR836 change to 63.4K from 69.8K PR846 and PR867 change to 3.09K from 3.32K PC9002,PC9003,PC9099,PC9098,PC9014,PC9091,PC9048 change to dummy	2/8	
12		1. prevent N17S design change 2. 5V voltage change to 5.2V 3. HW request 4. add filter 5. for mode change			1. PR701,PR1204,PR718,PR1201,PR1217 change to Oohm from R-short 2. PR401 change to 31.6K from 30.9K 3. add PR1232 for VGA_CORE_PG and PU to +3VS_1.8VSDGPU_AON. 4. PR1223 change to un-pop PC836 and PC837 change to pop PR875 and PR876 change to 10ohm PR908 change to 0 ohm 5. PU901 and PU902 change toNCP81151MNTBG_DFN8_2X2 PU903 change to NCP81253MNTBG_DFN8_2X2	2/9	
13		power squence			PC1209 change to unpop PR1231 change to R-short	2/10	
14		5V OCP level change			PR406 change 105K from 107K	2/19	
15		VGA Voltage overshoot reduce part count VRAM fix 1.35V			add PC1232 0.033uF PR718,PR1015,PR1013,PR1101,PR1204,PR1201,PR1217,PR1002change to R-short PR1010,PQ1001,PR1009,PR1011 remove from BOM	3/15	
16		component rating Add RC delay			PC1215 and PC1219 size change to 0603 from 0402 PR320 change to 499 ohm PC323 change to pop 2.2uF	3/24	

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HW Schematic chang list (P.I.R)

Item	Page	Date	Rev.	Reason for change	Modify Item
1	35	1/23	1.0	Type-C change connector	JUSB4 Symbol change to LOTES_AUSB0249-P001A_24P-T
2	38	1/23	1.0	Modify BOM structure	LK2, DK2 Change to FPENC@
3	39	1/23	1.0	ME Drawing update	H30,H29 Change to H_3P2
4	30	1/23	1.0	Update for SD Card write protect issue	Add QL1 & RL20, RL21, RL22 for SD_WP inverter circuit
5	31,33,35	1/23	1.0	Change 0 ohm to R-Short	RM9,RO3,RS10,RM23,RS37,RS38 Change to R-short
6	19	1/23	1.0	For acer lesson learnt V1.7	RD202 Change to 0 ohm (DDR_DRAMRST#) Reserve CC131 on EC_VCCST_PG Add RC20 10_0402_5% ohm (PCH_PWROK) POP CC123 AND Change to 10U_0603
7	36	1/23	1.0	Cap. package Change	CS24 Change to 0402 package
8	33	1/23	1.0	Remove un-use connector	Del JHDD1
9	31	1/23	1.0	Follow ESD request	POP CM15 with 1000pf
10	22	1/23	1.0	Update VGA Power Sequence(+1.05VS_1.0VSDGPU)	Unpop RV103, CV231 Add RV188 from VGA_CORE_PG
11	32	1/23	1.0	EMI Requirement change to 220ohm bead	Change RA34 to SM01000NY00(BLM15PX221SN1D) with EMI@
12	22	2/7	1.0	Add N17S Component for BOM Select	Add UGPU1 SA0000ANV00 with N17SG1@ Change BOM structure from GTR@ to N16SGTR@ Del UGPU1 for GMR1@ Add X7607@,X7608@,X7609@
13	12,35	2/7	1.0	Change 0 ohm to R-Short	RC195, RC204, RS1,RS2,RS3,RS4,RS5,RS6,RS7,RS8 change to R-Short
14	33	2/7	1.0	Adjust SATA TX redirver EQ for Parada IC	RO17, RO18 and RO19 change to X76PAR@
15	33	2/7	1.0	Update SATA redriver circuit for TI IC	Reserved RO26, RO27 with BOM strurture @ Add RO17, RO18 (4.7K), RO19, RO21 (0 ohm) with X76TI@
16	29,22	2/7	1.0	BOM Change	Pop CC58 with 10uF, unpop CC59
17	40	2/7	1.0	Update VGA Power Sequence	CV238, CV239 change to 680PF
18	8	2/7	1.0	Add CPU PN for DVT	Add UC1 PN for Intel i3,i5,i7 CPU
19	13,35	2/7	1.0	Remove un-use USB port(Port9)	Del LS24
20	35	2/7	1.0	Bom Change , pull up resistor change to 100K ohm	RS20, RS40,RS41 value change to 100k ohm
21	36	2/7	1.0	Cancel solder mask on co-lay pin	LS1,LS3,LS4,LS6 cover solder mask (footprint update)
22	36	2/8	1.0	For acer lesson learnt V1.7	CC65.1 change to PCH_PWROK_R
23	18	2/8	1.0	Adjust Crystal Cap value	CC128,CC129 change to 27pF
24	8	2/8	1.0	Update PCB PN	Add DAZ20X00201 and DA8001AU010 for PCB
25	32	2/8	1.0	Update BOM Structure	Change RA35 BOM Structure to EMI@
26	22	2/10	1.0	For N17S GC6 Discharge Sequence	Add DV10 Add RV189, CV263, DV11
27	9	2/10	1.0	Remove BIOM ROM socket (Debug only)	Del JC1
28	7,11,36	2/13	1.0	For acer lesson learnt V1.7	Add CC132 Change to 1000pF --> CC50, CC53,CC131,CS24,CC65
29	36	2/13	1.0	Change Cap material for Z-High issue	Change CS25 to SGA00009M00
30	21,30	2/15	1.0	Change R for 25M/27M Crystal	Change R4961 and RL14 to 1K
31	21	2/16	1.0	Change 27MHz Material	X2000 change from SJ10000UI00 to SJ10000TQ00
32	18	2/16	1.0	Connect UC1.F65/G65 to GND, Change AY3, AY71 NC	Add RC237, Change RC182,RC183 to 0 ohm(@)

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